Overview

HP Z8 G4 Workstation



1. Integrated Front Handle

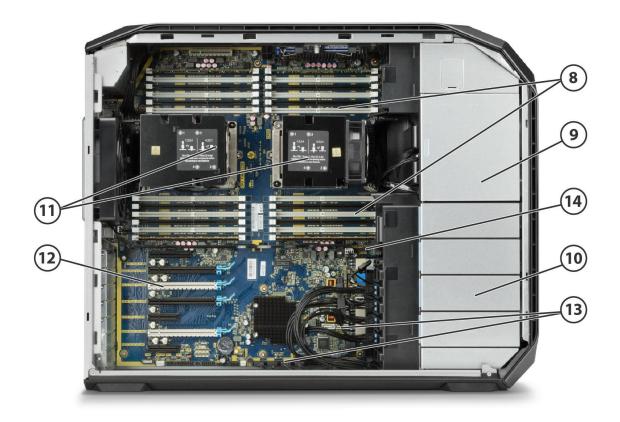
- 2. Dedicated 9.5mm Optical Drive Bay
- 3. Power Button
- 4. HDD Activity LED

Front view

- Front I/O Entry: 4 USB 3.1 Gen1 (Left-most Port has Charging Capability)
 Front I/O Premium: 2x USB 3.1 Gen1, 2x USB 3.1 Gen2 Type-C™ (Left-most Type-A Port has Charging Capability)
 Note: Premium Front IO is shown on Photography
- 6. Media Card Reader
- 7. 1 Headset



Overview



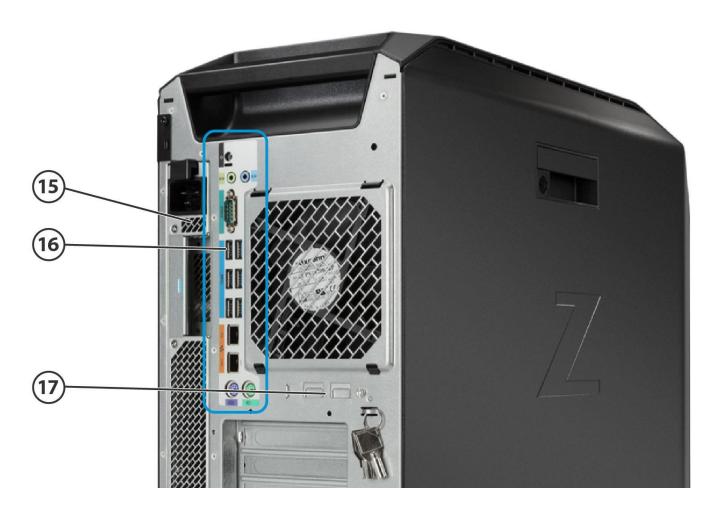
- 8. 24 DIMM Slots for DDR4 ECC Memory
- 9. 2 External 5.25" Bays and Slimline Optical
- 10. 4 Internal 3.5" Bays
- 11. 2 Intel® Xeon® Processors (Skylake SP) family

Internal view

- 12. Slot 1: PCIe Gen3 x4 Transforms to PCIe Gen3 x8 when 2nd CPU is installed
 - Slot 2: PCle Gen3 x16
 - Slot 3: PCIe Gen3 x16 Available ONLY when 2nd processor is installed
 - Slot 4: PCIe Gen3 x16
 - Slot 5: PCIe Gen3 x4
 - Slot 6: PCIe Gen3 x16 Available ONLY when 2nd processor is installed
 - Slot 7: PCIe Gen3 x4
- 13. 2 sSATA, 8 SATA (AHCI) Ports
- 14. 3 USB 2.0 Internal Ports, 1 USB 3.0 Gen1 Internal Port



Overview



Rear view

- 15. Choice of 1125W or 1450W, 90% Efficient Power Supplies
- 16. Rear I/O:

Rear Power Button

6 USB 3.1 Gen1

1 Serial

PS/2 keyboard and mouse

2 RJ-45 to integrated Gigabit LAN

1 Audio Line-In (can be retasked as microphone)

1 Audio Line-Out

17. Optional: 2 10GbE LAN ports

Overview

Overview

Form Factor Operating Systems

Tower

Preinstalled:

- Windows 11 Pro for Workstations²
- Windows 10 Pro for Workstations^{1,2}
- Ubuntu 20.04 LTS³
- HP Linux-ready (minimal OS ready for customer OS installation)
- Red Hat® Enterprise Linux® Desktop Workstation (Paper license with 1-year support; no preinstalled OS)

Supported:

- Red Hat[®] Enterprise Linux[®] Workstation 6, 7, 8⁴
- SUSE Linux® Enterprise Desktop 12, 15⁴
- Ubuntu 16.04, 18.04, 20.04 LTS³

²Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows is automatically updated and enabled. High speed internet and Microsoft account required. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.

³ Not all features are available in all editions or versions of Ubuntu. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS to take full advantage of Ubuntu functionality. Ubuntu may be automatically updated. ISP fees may apply, and additional requirements may apply over time for updates.

⁴**Notes**: For detailed Linux® OS/hardware support information, see: http://www.hp.com/support/linux_hardware_matrix

Note: In accordance with Microsoft's support policy, HP does not support the Windows® 7 operating system on products configured with Intel® 7th Generation and forward processors.

Available Processors

Name	Cores	Clock Speed (GHz)	Cache (MB)	Memory Speed (MT/s)	Hyper- Threading	Intel® Turbo Boost Technology ¹	Supports Intel® DCPMM® Technology ²	TDP (W)
Intel® Xeon® Platinum 8260L processor	24	2.4 GHz	35.75	2933	YES	3.1, 3.9	YES	165
Intel® Xeon® Gold 6258R processor	28	2.7 GHz	38.50	2933	YES	4.0, 3.4	YES	205
Intel® Xeon® Gold 6248R processor	24	3.0 GHz	35.75	2933	YES	4.0, 3.6	YES	205
Intel® Xeon® Gold 6246R processor	16	3.4 GHz	35.75	2933	YES	4.1, 4.0	YES	205
Intel® Xeon® Gold 6244 processor	8	3.6 GHz	24.75	2933	YES	4.3, 4.4	YES	150
Intel® Xeon® Gold 6242R processor	20	3.1 GHz	35.75	2933	YES	4.1, 3.8	YES	205



¹ Device comes with Windows 10 and a free Windows 11 upgrade or may be preloaded with Windows 11. Upgrade timing may vary by device. Features and app availability may vary by region. Certain features require specific hardware (see Windows 11 Specifications).

Overview

Intel® Xeon® Gold 6242 processor	16	2.8 GHz	22	2933	YES	3.5, 3.9	YES	150
Intel® Xeon® Gold 6240R processor	24	2.4 GHz	35.75	2933	YES	4.0, 3.2	YES	165
Intel® Xeon® Gold 6240 processor	18	2.6 GHz	24.75	2933	YES	3.3, 3.9	YES	150
Intel® Xeon® Gold 6238R processor	28	2.2 GHz	38.5	2933	YES	4.0, 3.0	YES	165
Intel® Xeon® Gold 6234 processor	8	3.3 GHz	24.75	2933	YES	4.0	YES	130
Intel® Xeon® Gold 6230R processor	26	2.1 GHz	35.75	2933	YES	4.0, 3.0	YES	150
Intel® Xeon® Gold 6226R processor	16	2.9 GHz	22	2933	YES	3.9, 3.6	YES	150
Intel® Xeon® Gold 6226 processor	12	2.7 GHz	19.25	2933	YES	3.5, 3.7	YES	125
Intel® Xeon® Gold 6136 processor	12	3.0 GHz	24.75	2666	YES	3.6, 3.7	NO	150
Intel® Xeon® Gold 6128 processor	6	3.4GHz	19.25	2666	YES	3.7, 3.7	NO	115
Intel® Xeon® Gold 5222 processor	4	3.8 GHz	16.5	2666	YES	3.9, 3.9	YES	105
Intel® Xeon® Gold 5220R processor	24	2.2 GHz	35.75	2666	YES	4.0, 2.9	YES	150
Intel® Xeon® Gold 5218R processor	20	2.1 GHz	27.5	2666	YES	4.0, 2.9	YES	125
Intel® Xeon® Gold 5218 processor	16	2.3 GHz	22	2666	YES	2.8, 3.9	YES	125
Intel® Xeon® Gold 5215 processor	10	2.5 GHz	13.75	2666	YES	3.0, 3.4	YES	85
Intel® Xeon® Gold 5118 processor	12	2.3 GHz	16.50	2400	YES	2.7, 3.2	NO	105
Intel® Xeon® Silver 4216 processor	16	2.1 GHz	22	2400	YES	2.7, 3.2	NO	100
Intel® Xeon® Silver 4215R processor	8	3.2 GHz	11	2400	YES	4.0, 3.6	YES	130
Intel® Xeon® Silver 4214R processor	12	2.4 GHz	16.5	2400	YES	3.0, 3.5	NO	100
Intel® Xeon® Silver 4214 processor	12	2.2 GHz	16.5	2400	YES	2.7, 3.2	NO	85
Intel® Xeon® Silver 4210R processor	10	2.4 GHz	13.75	2400	YES	2.9, 3.2	NO	100
Intel® Xeon® Silver 4210 processor	10	2.2 GHz	13.75	2400	YES	2.7, 3.2	NO	85
Intel® Xeon® Silver 4208 processor	8	2.1 GHz	11	2400	YES	2.5, 3.2	NO	85
Intel® Xeon® Silver 4114 processor	10	2.2 GHz	13.75	2400	YES	2.5, 3.0	NO	85
Intel® Xeon® Silver 4108 processor	8	1.8 GHz	11.00	2400	YES	2.1, 3.0	NO	85
Intel® Xeon® Bronze 3206R processor	8	1.9 GHz	11.00	2133	YES	N/A	NO	85
Intel® Xeon® Bronze 3204 processor	6	1.9 GHz	8.25	2133	YES	N/A	NO	85



Overview

All Z8G4 Intel® Xeon® CPUs Feature Intel® vPro™ Technology.

¹The specifications shown in this column represent the following: (all core maximum turbo steps, one core maximum turbo steps). Turbo boost stepping occurs in 100MHz increments. Processors that do not have turbo functionality are denoted as N/A.

Available Processors

Disclaimers

When ordering two processors, the second processor must be the same as the first. Intel processor numbers are not a measurement of higher performance. Processor numbers differentiate features within each processor family, not across different processor families.

Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

Color Black

Convertibility No

Expansion Slots (see system board section for more details)

Slot 1:

system board section for PCIe Gen3 x4 - Transforms to PCIe Gen3 x8 when 2nd CPU is installed

Slot 2:

PCIe Gen3 x16

Slot 3:

PCIe Gen3 x16 - Available ONLY when 2nd processor is installed

Slot 4:

PCIe Gen3 x16

Slot 5:

PCIe Gen3 x4

Slot 6:

PCIe Gen3 x16 - Available ONLY when 2nd processor is installed

Slot 7: PCIe Gen3 x4

Note: The PCIe x4 and PCIe x8 connectors above are open ended, allowing a PCIe x16 card to be seated in the slot.

Expansion Bays (see storage section for more details)

4 internal 3.5" bays (All 4 include acoustic dampening rail assemblies) 2 external 5.25" bays (175mm depth limit)

1 dedicated 9.5mm slim optical disk drive bay

Front I/O

- Base: 4 USB 3.1 Gen1 Type-A connector. Left most connector has charging capability, 1 Combo Headset, 1 Optional Media Card Reader
- Premium: 2 USB 3.1 Gen1 Type-A connector. Left most connector has charging capability, 2 USB 3.1 Gen2 Type-C[™] connector, 1 Combo Headset, 1 Optional Media Card Reader



Overview

Internal I/O Internal Slot 1 CPU1: PCIe Gen3 x8 - always available

Internal Slot 2 CPU2: PCIe Gen3 x8 - available when 2nd CPU is installed

2 USB 2.0 ports available with a single 2x5 header

1 USB 2.0 port available with a 1x6 header

1 USB 3.1 Gen1 and 1 USB 2.0 port available with a 2x6 header

Notes: The 2x5 header can be converted to a standard (Type-A) USB 2.0 connector through the use of one HP Internal USB Port Kit (EM165AA). This port kit uses one half of the 2x5 header.

The 1x6 header can be converted to a standard (Type-A) USB 2.0 connector through the use of one HP Internal USB Port Kit (EM165AA). This port kit uses 5 pin positions on the header.

The 2x6 header can be converted to a standard (Type-A) USB 2.0 connector through the use of one HP Internal USB Port Kit (EM165AA). This port kit

uses one half of the 2x6 header.

Rear I/O 6 USB 3.1 Gen1 (aka USB 3.0), 1 Serial, PS/2 keyboard and mouse, 2 RJ-45 to integrated Gigabit LAN, 1

Audio Line-In (can be retasked as microphone), 1 Audio Line-Out

Optional: 2 RJ-45 to 10GbE LAN ports

Interfaces Supported 10 channel SATA 6.0 Gb/s interface

Factory integrated RAID available for SATA drives (RAID 0, 1 and 10)

Internal USB 3.1 Gen1, USB 3.1 Gen2, USB 2.0

On-board RAID Support SATA RAID 0 Striped Array

SATA RAID 1 Mirrored Array SATA RAID 10 Striped/Mirrored SATA RAID 5 Parity Array

Chassis Dimensions (H x

W x D)

Footprint: H: 17.5" [444.5mm]

W: 8.5" [215.9mm]

D: 21.7" [551.2mm] (measured to the rear of service panel)

Maximum: H: 17.5" [444.5mm]

W: 8.5" [215.9mm]

D: 21.85" [555.2mm] (measured to the embossment for the rear chassis fans)

Packaged Dimensions H: 25" (636mm)

W: 13.1" (332mm) D: 28.9" (734mm)

Palletization Profile 4 units x 3 layers = 12 units per pallet

1200x1000x2034mm (pallet included)

Rack Dimensions 5U

Weight Exact weights depend upon configuration (System weight only).

Minimum: 22.4kg (49.4lbs.) Typical: 23.7kg (52.2lbs.) Maximum: 31.7kg (70lbs.)

Temperature Operating: 5° to 35°C (40° to 95°F)

Non-operating: -40° to 60°C (-40° to 140°F)

Humidity Operating: Operating: 10% to 85% RH, non-condensing, 35° C maximum wet bulb

Non-operating: 10% to 90%, non-condensing, 35° C maximum wet bulb

Overview

Maximum Altitude (nonpressurized) Operating: 3,048m (10,000ft) Non-operating: 9,144m (30,000ft)

Note: Above 1524 m (5,000 feet) altitude, maximum operating temperature is reduced by 1° C (1.8° F) per 305 m (1,000 feet) elevation increase

Power Supply

Choice of:

1125W/100V/15A 90% Efficient wide-ranging, active Power Factor Correction The power delivery system includes four 6+2-pin graphics power cables.

1450W/200V/10A 90% Efficient wide-ranging, active Power Factor Correction The power delivery system includes four 6+2-pin graphics power cables.

Available in limited regions

1450W/100V/20A 90% Efficient wide-ranging, active Power Factor Correction The power delivery system includes four 6+2-pin graphics power cables.

1700W/200V/10A 90% Efficient wide-ranging, active Power Factor Correction The power delivery system includes four 6+2-pin graphics power cables.

Notes: The 1125W/100V/15A (1450W at 200V Input Voltage) power supply can also supply 1275W of output power when the input voltage is greater than 105V. If the input voltage is less than 105V, but greater than 90V for any reason, the maximum power that can be drawn is 1125W. An uninterruptible power supply (UPS) is highly recommended if 1275W output power is desired.

The 1125W Power Supply can also supply 1450W of output power when the input voltage is greater than 200V under all conditions.

The 1450W/100V/20A (1700W at 200V Input Voltage) power supply can also supply 1550W of output power when the input voltage is greater than 105V. If the input voltage is less than 105V, but greater than 90V for any reason, the maximum power that can be drawn is 1450W. An uninterruptible power supply (UPS) is highly recommended if 1550W output power is desired.

The 1450W Power Supply can also supply 1700W of output power when the input voltage is greater than 200V under all conditions.

The 1450W/100V/20A chassis is shipped with a 20A power cord and requires a 20A outlet in an environment with 100V/110V. Site modification may be required. Check with your sales lead and click here for the Site Prep Guide.

The Z8 G4 power supply efficiency reports can be found at these links:

1125W - Link:

https://plugloadsolutions.com/psu_reports/HP%20Inc_DPS-1125BB%20A_1125W_ECOS%204825_Report.pdf

1450W - Link:

https://plugloadsolutions.com/psu_reports/HP%20Inc_DPS-1450AB%20A 1450W ECOS%204826 Report.pdf

Workstation ISV Certifications See the latest list of certifications at

http://www.hp.com/united-states/campaigns/workstations/partnerships.html

Supported Components

Processors

Intel® Xeon® processor Scalable family	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
Intel® Xeon® Platinum 8260L processor	Υ	Υ	170R9AA	1
Intel® Xeon® Gold 6258R processor	Υ	Υ	9VA96AA	1
Intel® Xeon® Gold 6248R processor	Υ	Υ	9VA93AA	1
Intel® Xeon® Gold 6246R processor	Υ	Υ	9VA92AA	1
Intel® Xeon® Gold 6244 processor	Υ	Υ	5YZ47AA	1
Intel® Xeon® Gold 6242R processor	Υ	Υ	9VA91AA	1
Intel® Xeon® Gold 6242 processor	Υ	Υ	5YZ46AA	1
Intel® Xeon® Gold 6240R processor	Υ	Υ	9VA90AA	1
Intel® Xeon® Gold 6240 processor	Υ	Υ	5YZ44AA	1
Intel® Xeon® Gold 6238R processor	Υ	Υ	9VA89AA	1
Intel® Xeon® Gold 6234 processor	Υ	Υ	5YZ42AA	1
Intel® Xeon® Gold 6230R processor	Υ	Υ	9VA88AA	1
Intel® Xeon® Gold 6226R processor	Υ	Υ	9VA86AA	1
Intel® Xeon® Gold 6226 processor	Υ	Υ	5YZ40AA	1
Intel® Xeon® Gold 6136 processor	Υ	Υ	1XM62AA	1
Intel® Xeon® Gold 6128 processor	Υ	Υ	1XM69AA	1
Intel® Xeon® Gold 5222 processor	Υ	Υ	5YZ39AA	1
Intel® Xeon® Gold 5220R processor	Υ	Υ	8BD06AA/AT	1
Intel® Xeon® Gold 5218R processor	Υ	Υ	9VA84AA	1
Intel® Xeon® Gold 5218 processor	Υ	Υ	5YZ37AA	1
Intel® Xeon® Gold 5215 processor	Υ	Υ	5YZ35AA	1
Intel® Xeon® Gold 5118 processor	Υ	Υ	1XM71AA	1
Intel® Xeon® Silver 4216 processor	Υ	Υ	5YZ34AA	1
Intel® Xeon® Silver 4215R processor	Υ	Υ	9VA82AA	1
Intel® Xeon® Silver 4214R processor	Υ	Υ	8BD03AA/AT	1
Intel® Xeon® Silver 4214 processor	Υ	Υ	5YZ32AA	1
Intel® Xeon® Silver 4210R processor	Υ	Υ	8BD02AA	1
Intel® Xeon® Silver 4210 processor	Υ	Υ	5YZ31AA	1
Intel® Xeon® Silver 4208 processor	Υ	Υ	5YZ30AA	1
Intel® Xeon® Silver 4114 processor	Υ	Υ	1XM74AA	1
Intel® Xeon® Silver 4108 processor	Υ	Υ	1XM76AA	1
Intel® Xeon® Bronze 3206R processor	Υ	Υ	8BD00AA	1
Intel® Xeon® Bronze 3204 processor	Υ	Υ	5YZ29AA	1
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¹ Options kits available for second processor upgrade.

Disclaimers: When ordering two processors, the second processor must be the same as the first. Intel processor numbers are not a measurement of higher performance. Processor numbers differentiate features within each processor family, not across different processor families.

Note 1: Intel® DCPMM® (Data Center Persistent Memory) Supported.



Supported Components

Monitors / Displays	Factory Configured Option Kit	Option Kit Part Number	Support Notes
HP Z Display Z22n G2	Υ	1JS05AA	
HP Z Display Z23n G2	Υ	1JS06AA	
HP Z Display Z24i G2	Υ	1JS08AA	
HP Z Display Z24n G2	Υ	1JS09AA	
HP Z Display Z24nf G2	Υ	1JS07AA	
HP Z Display Z27n G2	Υ	1JS10AA	
HP Z Display Z27s (4K disp	olay) Y	J3G07AA	
Supported by all operating Screen size measured diag	g systems available from HP gonally		

Storage / Hard Drives

SAS Hard Drives	SAS Hard Drives for HP Workstations	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	HP 300GB 15k SAS SFF	Υ	Υ	L5B74AA	
	NOTE: SAS controller add-in card required				

SATA Hard Drives		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	SATA (Serial ATA) Hard Drives for HP Workstations				
	500GB SATA 7200RPM 6Gb/s 3.5" HDD	Υ	Υ	LQ036AA	
	500GB SATA 7200RPM 6Gb/s OPAL2 SFF 3.5" HDD	Υ	Υ	D8N29AA	
	1TB SATA 7200RPM 3.5" HDD	Υ	Υ	LQ037AA	
	1TB SATA 7200RPM Ent 3.5" HDD	Υ	Υ	WOR10AA	
	2TB SATA 7200RPM HDD CMR	Υ	Υ	QB576AA	
	2TB SATA 7200RPM HDD SMR				
	2TB 7200RPM SATA 3.5in Enterprise	Υ	Υ	2Z274AA	
	4TB SATA 7200RPM Ent 3.5" HDD	Υ	Υ	K4T76AA	
	6TB SATA 7200RPM Ent 3.5" HDD	Υ	Υ	3DH90AA	
	8TB 7200RPM SATA 3.5in Enterprise	Υ	Υ	2Z273AA	
	NOTES:				

Up to (5) 3.5-inch 7200 rpm SATA drives: 500 GB, 1.0, 2.0, 4.0 TB; 20TB max total

Supported Components

SATA Solid State Drives		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	HP Solid State Drives (SSDs) for Workstations				
	HP 256GB SATA SSD	Υ	Υ	A3D26AA	
	HP 512GB SATA SSD	Υ	Υ	D8F30AA	
	HP 1TB SATA SSD	Υ	Υ	F3C96AA	
	HP 2TB SATA SSD	Υ	Υ	Y6P08AA	
	HP 256GB SATA SED OPAL2 SSD	Υ	Υ	G7U67AA	
	HP 512GB SATA SED OPAL2 SSD	Υ	Υ	N8T26AA	
	HP 240GB SATA Enterprise SSD	Υ	Υ	T3U07AA	
	HP 480GB SATA Enterprise SSD	Υ	Υ	T3U08AA	
	960GB 2.5in Enterprise SATA-3 SSD	Υ	Υ	1W6P8AA	
	1920GB 2.5in Enterprise SATA-3 SSD	Υ	Υ	1W6P9AA	

PCIe Solid State Drives		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	PCIe SSDs for HP Workstations				
	HP Z Turbo Drive 256GB MLC Z8G4 SSD Module	N	N	EOL	5
	HP Z Turbo Drive 512GB MLC Z8G4 SSD Module	N	N	EOL	5
	HP Z Turbo Drive 1TB MLC Z8G4 SSD Module	N	N	EOL	5
	HP Z Turbo Drive 256GB TLC Z8G4 SSD Module	Υ	Υ	1PD53AA	2
	HP Z Turbo Drive 512GB TLC Z8G4 SSD Module	Υ	Υ	1PD54AA	2
	HP Z Turbo Drive 1TB TLC Z8G4 SSD Module	Υ	Υ	1PD55AA	2
	HP Z Turbo Drive 2TB TLC Z8G4 SSD Module	Υ	Υ	3KP41AA	2
	HP Z Turbo Drive 256GB SED Z8G4 SSD Module	N	N	EOL	5
	HP Z Turbo Drive 512GB SED Z8G4 SSD Module	N	N	EOL	5
	HP Z Turbo Drive 256GB MLC Z8 G4 SSD Kit	N	N	EOL	5
	HP Z Turbo Drive 512GB MLC Z8 G4 SSD Kit	N	N	EOL	5
	HP Z Turbo Drive 1TB MLC Z8 G4 SSD Kit	N	N	EOL	5
	HP Z Turbo Drive 256GB TLC Z8 G4 SSD Kit	Υ	Υ	1PD47AA	4
	HP Z Turbo Drive 512GB TLC Z8 G4 SSD Kit	Υ	Υ	1PD48AA	4
	HP Z Turbo Drive 1TB TLC Z8 G4 SSD Kit	Υ	Υ	1PD49AA	4
	HP Z Turbo Drive 2TB TLC Z8 G4 SSD Kit	Υ	Υ	3KP40AA	4
	HP Z Turbo Drive 256GB SED Z8 G4 SSD Kit	Υ	Υ	2SA33AA	4
	HP Z Turbo Drive 512GB SED Z8 G4 SSD Kit	Υ	Υ	2SA35AA	4
	HP Z Turbo Drive 1TB SED Z8 G4 SSD Kit	Υ	Υ	6YT75AA	4
	HP Z Turbo Drive 1TB SED Z8 G4 SSD Module	Υ	Υ	6YT79AA	2
	HP Z Turbo 2TB SED OPAL2 TLC M.2 Z8 SSD	Υ	Υ	2Y7W7AA	
	HP 1x256GB M.2 2280 PCIe NVMe TLC SSD Z8 G4 Kit	Υ	Υ	8PE71AA	3
	HP 1x512GB M.2 2280 PCIe NVMe TLC SSD Z8 G4 Kit	Υ	Υ	8PE72AA	



Supported Components

HP 1x1TB M.2 2280 PCIe NVMe TLC SSD Z8 G4 Kit	Υ	Υ	8PE73AA	3
HP 256GB M.2 2280 PCIe NVMe TLC SSD Module	N	Υ	8PE62AA	2
HP 512GB M.2 2280 PCIe NVMe TLC SSD Module	N	Υ	8PE63AA	2
HP 1TB M.2 2280 PCIe NVMe TLC SSD Module	N	N	8PE64AA	2
HP 2TB PCIe NVME TLC M.2 Z8 G4 SSD	Υ	Υ	307N2AA	
HP Z Turbo Drive Quad Pro				
HP Z Turbo Drive Quad Pro 2x256GB PCIe TLC SSD	Υ	Υ	4YZ38AA	1
HP Z Turbo Drive Quad Pro 2x512GB PCIe TLC SSD	Υ	Υ	4YZ39AA	1
HP Z Turbo Drive Quad Pro 2x1TB PCIe TLC SSD	Υ	Υ	4YZ40AA	1
HP Z Turbo Drive Quad Pro 2x2TB PCIe TLC PCIe SSD	Υ	Υ	3KP42AA	
HP Z Turbo Drive Quad Pro 256GB TLC SSD module	N	Υ	4YZ35AA	2
HP Z Turbo Drive Quad Pro 512GB TLC SSD module	N	Υ	4YZ36AA	2
HP Z Turbo Drive Quad Pro 1TB TLC SSD module	N	Υ	4YZ37AA	2
HP Z Turbo Drive Dual Pro				
HP Z Turbo Drive Dual Pro 256GB TLC SSD	Υ	Υ	4YF60AA	3
HP Z Turbo Drive Dual Pro 512GB TLC SSD	Υ	Υ	4YF61AA	3
HP Z Turbo Drive Dual Pro 1TB TLC SSD	Υ	Υ	4YF62AA	3
HP Z Turbo Drive Dual Pro 2TB TLC SSD	Υ	Υ	4YF63AA	3
HP 256GB M.2 2280 PCIe NVMe TLC SSD Dual Pro Kit	Υ	Υ	8PE74AA	3
HP 512GB M.2 2280 PCIe NVMe TLC SSD Dual Pro Kit	Υ	Υ	8PE75AA	3
HP 1TB M.2 2280 PCIe NVMe TLC SSD Dual Pro Kit	Υ	Υ	8PE76AA	3
Intel® 905p Series SSD (Opatane SSD)				
Intel® Optane SSD 905p 280GB AiC**	Υ	Υ	2SC47AA	
Intel® Optane SSD 905p 480GB AiC**	Υ	Υ	2SC48AA	
Intel® Optane SSD 905p 380GB M.2 SSD Module	Υ	Υ	6LA66AA	

NOTE 1: Dual M.2 SSD drive plus Quad Pro carrier

NOTE 2: M.2 SSD drive only designed to be installed in Quad Pro, Dual Pro or personality module

NOTE 3: Kit includes single M.2 SSD, dual pro carrier and heat sink

NOTE 4: Kit includes single M.2 SSD, dual personality module carrier and heat sink

NOTE 5: These M.2 SSD Kits and modules are End of Life and no longer available.

*For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30GB of system disk is reserved for system recovery software

^{**} PCIe card installed in standard PCIe x4 slot

Hard Drive Controllers		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	SAS Controller				
	MicroSemi SmartHBA2100-4i4e SAS Controller	Υ	Υ	1FV90AA	

Graphics

Factory Option Option Kit Part Support Supported Configured Kit Number Notes # of cards



Supported Components

Graphics Cable Adapters				
HP miniDP-to-DP Adapter	Υ	Υ		
HP miniDP-to-DP Adapter (2-pack)	Υ	N		
HP miniDP-to-DP Adapter (4-pack)	Υ	N		
HP miniDP-to-DP Adapter (8-pack)	Υ	N		
HP DisplayPort to Dual Link DVI Adapter	Υ	Υ	NR078AA	
HP DisplayPort to DVI-D Adapter	Υ	Υ	FH973AA	
HP DisplayPort to DVI-D Adapter (2-pack)	Υ	N		
HP DisplayPort to DVI-D Adapter (4-pack)	Υ	N		
HP DisplayPort to DVI-D Adapter (6-pack)	Υ	N		
HP DisplayPort to VGA Adapter	Υ	Υ	AS615AA	
HP DisplayPort to HDMI Adapter	Υ	Υ	K2K92AA	
NVIDIA SLI 2-slot Graphics Connector	Υ	Υ	2YY84AA	
Quadro RTX NVLink High-Bandwidth 2-slotBridge (RTX 8000, RTX 6000)	N	Υ	6FY11AA	
Quadro RTX NVLink 2-slotBridge (RTX 5000)	Υ	Υ	6FY12AA	
NVIDIA NVLink 2-Slot Bridge (RTX A6000, RTX A5000)	N	Υ	340L2AA	
Entry 3D				
NVIDIA® Quadro® P400 2GB Graphics	Υ	Υ	1ME43AA	2
NVIDIA® Quadro® P620 2GB Graphics	Υ	Υ	3ME25AA	2
NVIDIA® T400 2 GB GDDR6 LP Blower Fan 3mDP PCIe x16 Graphics	Υ	Υ	340K8AA	2
NVIDIA® T600 4 GB GDDR6 LP Blower Fan 4mDP PCIe x16 Graphics	Υ	Υ	340K9AA	2
Mid-range 3D				
NVIDIA® Quadro® P1000 4GB Graphics	Υ	Υ	1ME01AA	4
NVIDIA® Quadro® P2000 5GB Graphics	Υ	Υ	1ME41AA	4
NVIDIA® Quadro® P2200 5GB Graphics	Υ	Υ	6YT67AA	4
AMD Radeon™ Pro WX 3200 4GB Graphics	Υ	Υ	6YT68AA	4
NVIDIA® T1000 4 GB 4mDP Graphics	Υ	Υ	20X22AA/AT	3
NVIDIA RTX A2000 6 GB 4mDP Graphics	Υ	Υ	340L0AA	3
High End 3D				
NVIDIA® Quadro RTX 4000 8GB Graphics	Υ	Υ	5JV89AA	3
NVIDIA® RTX A4000 16 GB 4DP Graphics	Υ	Υ	20X24AA/AT	4
NVIDIA® RTX A4500 20 GB GDDR6 4DP Graphics	Υ	Υ	5S458AA/AT	3
AMD Radeon™ Pro W5500 8GB 4DP GFX	Υ	Υ	9GC16AA/AT	3
AMD Radeon™ Pro W5700 8GB 5mDP+USBc GFX	Υ	Υ	9GC15AA/AT	2
Ultra High-End 3D				
NVIDIA® Quadro® GV100 32GB Graphics	Υ	Υ	3ME26AA	3
NVIDIA® Quadro RTX 5000 16GB Graphics	Υ	Υ	5JH81AA	2
NVIDIA® RTX A5000 24 GB Graphics	Υ	Υ	20X23AA	3
NVIDIA® RTX A6000 48GB Graphics	Υ	Υ	2S6U3AA	2
AMD Radeon Pro W6800 32GB Graphics	Υ	Υ	340K7AA	2
NVIDIA® Quadro® Sync II	Υ	Υ	1WT20AA	



Supported Components

Memory		SL Processor	CL Processor	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	DDR4-2666 ECC Registered DIMMs						
	8GB (1x8GB) DDR4-2666 ECC Reg Memory	Υ	N	Υ	Υ	1XD84AA	1,3
	16GB (1x16GB) DDR4-2666 ECC Reg Memory	Υ	N	N	Υ	1XD85AA	1,3
	32GB (1x32GB) DDR4-2666 ECC Reg Memory	Υ	N	N	Υ	1XD86AA	1,3
	64GB (1x64GB) DDR4-2666 ECC LR Memory	Υ	N	N	Υ	1XD87AA End of Life	1,2,3
	128GB (1x128GB) DDR4-2666 ECC 3DS LR Memory	Υ	N	N	Υ	3GE82AA End of Life	1,2,3
	8GB (1x8GB) DDR4-2933 ECC Reg Memory	Υ	Υ	Υ	Υ	5YZ56AA	1,3
	16GB (1x16GB) DDR4-2933 ECC Reg Memory	N	Υ	N	Υ	5YZ54AA	1,3
	32GB (1x32GB) DDR4-2933 ECC Reg Memory	N	Υ	N	Υ	5YZ55AA	1,3
	64GB (1x64GB) DDR4-2399 ECC Reg Memory	N	Υ	N	Υ	5YZ57AA	1.3

SL CPU: Are processors formerly known as Intel® Skylake that are sold under the model name Intel® Xeon® SP: Platinum 8100, Gold 6100, Gold 5100, Silver 4100 and Bronze 3100 Family

CL CPU: Are processors formerly known Intel® Cascade Lake that are sold under the model name Intel® Xeon® SP: Platinum 8200, Gold 6200, Gold 5200, Silver 4200 and Bronze 3200 Family

NOTES:

- 1. For details on the supported memory configurations on the HP Z8 G4 Workstation, please refer to the System Technical Specifications System Board section of this document.
- 2. Sleep (S3 state) support:
- Sleep (S3 state) may not be supported with non-HP validated and qualified 64 GB LR DIMMs.
- Sleep (S3 state) is not supported with 128 GB 3DS LR DIMMs
- 3. You cannot intermix different types of memory. The system will not work if LR DIMMs, RDIMMs or 3DS LR DIMMs are intermixed.

DIMMs should be equally distributed across all six memory channels for optimal performance.

Each processor supports up to 6 channels of DDR4 memory. To realize full performance at least 1 DIMM must be inserted into each channel.

The CPUs determine the speed at which the memory is clocked. If a 2400MT/s capable CPU is used in the system, the maximum speed the memory will run at is 2400MT/s, regardless of the specified speed of the memory.

MT/s = Million Transfers per second

The Z8 G4 is designed to work ONLY with DDR4 memory. The system will not work with DDR3 memory.

NOTE: Factory-configured CTO (xxxxxAV) and aftermarket AMO (xxxxxAA, xxxxxAT) HP memory part numbers designated as "2666" may ship with "2933" or "3200" speed memory components. Similarly, HP Memory part numbers designated as "2933" may ship with "3200" speed memory. This does not affect HP part number availability, nor does it affect system performance or operation. All hardware configurations currently supporting HP memory part numbers

Supported Components

designated as "2666" or 2933 have been fully qualified to work with fast speed memory and are fully supported by HP under standard support terms.

NVDIMM Memory		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	Intel® Optane™ DC Persistent Memory (DCPMM)				
	128GB (1x128GB) DC Persistent Memory Module	Υ	Υ	9NH78AA	1
	256GB (2x128GB) DC Persistent Memory Configuration	Υ	N		1
	256GB (1x256GB) DC Persistent Memory Module	N	Υ	4D8COAA	1
	512GB (4x128GB) DC Persistent Memory Configuration	Υ	N		1.2

NOTE 1: Supported only with Xeon 82xx, 62xx, 52xx and 4215/4215R processors.

- a. Available as factory configured in Memory Mode or Storage Mode.
 - i. Option Kit 4D8COAA is currently only supported in memory mode.
- b. Systems configured with DCPMM memory will operate the memory subsystem at 2666 MT/s.
- c. Operating System Support:
 - i. Windows 11 Pro for Workstations with all updates applied
 - ii. Windows 10 Pro for Workstations v1903 or later with all updates applied.
 - iii. Linux OS support may be found in the Linux Hardware Support Matrix.
- d. Detailed setup, security and support information may be found in the Intel® Optane™ DC Persistent Memory: Configuration and Setup on HP Z6 G4 and Z8 G4 Workstation white paper.
- e. DCPMM solutions require additional DRAM memory to be included in the solution:
 - i. Systems configured with DCPMM in Memory Mode will include DRAM memory to be used as cache. The amount of included DRAM memory is based on an 8:1 DCPMM to DRAM capacity ratio.
 - Systems configured with DCPMM in Storage Mode will require DRAM System Memory to be ordered separately.
 - iii. DCPMM Memory will report approximately 2% less than advertised capacity.
- f. Total Memory (DCPMM + DRAM) per processor must be <= 1TB or 2TB per dual processor system.
 - i. Z8 G4 Note: "M" processors support a total memory limit < =2TB per processors or 4TB per dual processor system
 - ii. When Configured in Memory Mode, additional DRAM does not count against maximum processor memory.
- g. Maximum number of DCPMM modules in a Z8G4 is 6 per processor.
- Customer is responsible for additional required DRAM when adding DCPMM modules in Memory Mode.
- HP Z8G4 configured with some AMD Graphics are limited to 1TB of total DCPMM and DRAM memory.
 See AMD Graphics specifications for details.

NOTE 2: Requires 2nd processor option.

Multimedia and Audio Devices



Supported Components

Multimedia and Audio Devices

Option Kit
Factory Part Support
Configured Option Kit Number Notes

Integrated Realtek HD ALC221 Audio

Optical and Removable Storage

-	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
HP SlimTray Optical Drives				
HP 9.5mm Slim Blu Ray Disc Writer	Υ	Υ	K3R65AA	1
HP 9.5mm Slim DVD ROM	Υ	Υ	K3R63AA	1
HP Half Height Optical Drives				
HP HH DVD Writer (16X RW DVD-R)	N	Υ	4AR67AA	
HP 9.5mm Slim DVD Writer*	Υ	Υ	K3R64AA	1
HP SD Card Reader				
HP SD 4 Card Reader	Υ	Υ	YOL99AA	
HDD Frame/Carriers				
HP DX175 Removable HDD Carrier	N	Υ	1ZX72AA	
HP DX175 Removable HDD Frame/Carrier	N	Υ	1ZX71AA	
NVMe Frame/Carrier				
HP QX310 Removable NVMe Frame/Carrier w/PCIe card	Υ	N		
HP QX310 Removable Carrier only	N	Υ	8GQ91AA/AT	

NOTE 1: Installing an optical drive into Z8 G4 requires a 5.25" external bay adapter.

*Actual speeds may vary. No support for DVD-RAM (DVD Writer). Does not permit copying of commercially available DVD movies or other copyright protected materials. Intended for creation and storage of your original material and other lawful uses. Double Layer discs can store more data than single layer discs. However, double-layer discs burned with this drive may not be compatible with many existing single-layer DVD drives and players.

With Blu-ray, certain disc, digital connection, compatibility and/or performance issues may arise, and do not constitute defects in the product. Flawless playback on all systems is not guaranteed. In order for some Blu-ray titles to play, they may require a DVI or HDMI digital connection and your display may require HDCP support. HD-DVD movies cannot be played on this workstation.

Networking and Communications

	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
Intel® 1350-T2 PCIe Dual Port Gigabit NIC	Υ	Υ	V4A91AA	
Intel® 1350-T4 PCIe 4-Port Gigabit NIC	N	Υ	W8X25AA	
Intel® Ethernet I210-T1 PCIe x1 Gb NIC	Υ	Υ	E0X95AA	
Aquantia® NBASE-T 5GbE PCIe NIC	N	Υ	1PM63AA	



Supported Components

Intel® X550-T2 10GbE Dual Port NIC	Υ	Υ	1QL46AA
Intel® X710-DA2 10GbE SFP+ Dual Port NIC	Υ	Υ	1QL47AA 1
HP 10GBASE-T Dual NIC Module Z6/8 G4	Υ	Υ	1QL49AA
Intel® 8265 802.11 a/b/g/n/ac&BT PCle	N	Υ	1QL48AA
Intel® 9260 802.11 a/b/g/n/ac&BT PCle	N	Υ	6SL33AA US/CAN only
HP 10GbE SFP+ SR 1st Transceiver	Υ	Υ	C3N53AA
Intel® Wi-Fi 6 AX200 & BT PCIe	N	Υ	7CE01AA
Intel AX210 Wi-Fi 6e non-vPro +Bluetooth 5.2 External Antenna WLAN	N	Y	340L7AA
Allied Telesis AT-2914SX/LC-901 1GB LC Fiber NIC Note 1: Windows 7 is NOT supported	Υ	Y	1C7Q2AA

Racking and Physical Security



Supported Components

Racking and Physical Security

	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
Security Cable with Kensington Lock	N	Υ	PC766A	
HP Chassis Intrusion Sensor	Υ	N		1
HP Z640/Z840/Z8G4 Rail Rack Kit	N	Υ	2FZ77AA	
HP Z8 Rack Rail Upgrade Kit	N	Υ	2FZ76AA	
HP Keyed Cable Lock 10mm	N	Υ	T1A62AA	
NOTE 1: Standard on all systems				

Input Devices

	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
HP Wireless Business Slim Keyboard and Mouse	Υ	Υ	N3R88AA	
Business Slim PS/2 Wired Keyboard	Υ	Υ	N3R86AA	
USB Business Slim Wired Keyboard	Υ	Υ	N3R87AA	
USB Premium Wired Keyboard	Υ	Υ	Z9N40AA	
USB Wired SmartCard CCID Keyboard	Υ	Υ	E6D77AA	
HP Optical USB Mouse	Υ	Υ	QY777AA	
HP PS/2 Mouse	Υ	Υ	QY775AA	
USB 1000dpi Laser Mouse	Υ	Υ	QY778AA	
HP USB Hardened Mouse	Υ	Υ	P1N77AA	
HP Creator 935 Black Wireless Mouse	N	Υ	1D0K8AA	
HP Wired 320M Mouse	Υ	Υ	9VA80AA	

Other Hardware

	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
HP Internal USB Port Kit	N	Υ	EM165AA	Note 1
HP eSATA PCI Cable Kit	Υ	Υ	GM110AA	Note 2
HP Optical Bay HDD Mounting Bracket	N	Υ	NQ099AA	Note 3
HP 2.5in HDD/SSD 2-in-1 ODD Bay Bracket	N	Υ	K4T74AA	Note 4
HP Z Premium Front I/O 2xUSB-A 2xUSB-C	N	Υ	1XM32AA	
HP Power Cord Kit	Υ	N		
HP Workstation Mouse Pad	Υ	N		Japan Only
HP ENERGY STAR® Certified Configuration	Υ	N		

NOTE 1: The HP Internal USB Port kit has a single USB 2.0 type A connector.

NOTE 2: No hot plug / hot swap supported with eSATA

NOTE 3: NQ099AA used to install greater than four 3.5" HDDs in the factory or when purchasing

Aftermarket Option (AMO) drives



Supported Components

NOTE 4: K4T74AA used to install greater than four 2.5" HDD/SSDs in the factory or when purchasing Aftermarket Option (AMO) drives

Application Software		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	Sobey Video Editing SW	Υ	N		China Only
	HP ZCentral Remote Boost	N	N		
	Data Science Stack	Υ	N		1, 2
	WSL2/Ubuntu Data Science Stack	Υ	N		1, 3
	*Not all Application Software for Z Desk Note 1: Only available with NVIDIA grap Note 2: Only available with Ubuntu 20.0 Note 3: Only available with Windows 10	hics cards selectior 04 LTS preinstall.	ns.	•	Workstations.

Supported Components

Operating Systems

Windows 11 Pro for Workstations

Windows 10 Pro for Workstations

Note 4,5

Windows 10 Pro for Workstations

Note 3,4,5

Ubuntu 20.04 LTS

HP Linux® Installer Kit

Note 2

Red Hat ® Enterprise Linux® (RHEL) Workstation - Paper License (1yr)

Note 1,2

NOTE 1: This second OS must be ordered with the HP Linux® Installer Kit as the first OS.

NOTE 2: For detailed Linux® OS/hardware support information, see:

http://www.hp.com/support/linux_hardware_matrix

NOTE 3: Device comes with Windows 10 and a free Windows 11 upgrade or may be preloaded with Windows 11. Upgrade timing may vary by device. Features and app availability may vary by region. Certain features require specific hardware (see Windows 11 Specifications).

NOTE 4: Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows is automatically updated and enabled. High speed internet and Microsoft account required. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.

NOTE 5: Available with Windows Subsystem for Linux® (WSL2).



System Technical Specifications

System Board

System Board Form Custom Form Factor, 16.34"x15.25" (415mm x 387.2mm)

Factor

Processor Socket Dual FCLGA3647 (Socket P)

CPU Bus Speed UPI: Up to 10.4GT/second, depending on processor

Chipset Intel® C622 Chipset **Super I/O Controller** Nuvoton SIO15

Memory Expansion Slots 24 slots (12 slots per CPU)

Memory Type Supported DDR4 R-DIMM (Registered), ECC: 8GB, 16GB, 32GB, and 64GB

DDR4 LR-DIMM (Load Reduced), ECC: 64GB

DDR4 3DS LR DIMM (3D Stacked, Load Reduced), ECC: 128GB* *128GB DIMMs are supported but no longer supplied by HP

Memory Modes NUMA (Non-Uniform Memory Architecture), Memory Node Interleave

2133MT/s, 2400MT/s, and 2666MT/s, and 2933MT/s

Memory Speed

Supported

Available Memory Configurations:

	Single Processor												
	CPU 0												
System			Top :	Slots					Bottor	n Slots			Perf
Memory	DIMM 1	DIMM 2	DIMM 3	DIMM 4	DIMM 5	DIMM 6	DIMM 7	DIMM 8	DIMM 9	DIMM 10	DIMM 11	DIMM 12	Rating
8GB	8GB												Fair
16GB	8GB											8GB	Good
24GB	8GB		8GB		8GB								Better
2200	8GB		8GB							8GB		8GB	Better
32GB	16GB											16GB	Good
40CD	8GB		8GB		8GB			8GB		8GB		8GB	Best
48GB	16GB		16GB		16GB								Better
CACD	16GB		16GB							16GB		16GB	Better
64GB	32GB											32GB	Good
	8GB	8GB	8GB	8GB	8GB	8GB	8GB	8GB	8GB	8GB	8GB	8GB	Best
96GB	16GB		16GB		16GB			16GB		16GB		16GB	Best
	32GB		32GB		32GB								Better
128GB	32GB		32GB							32GB		32GB	Better
10200	16GB	16GB	16GB	16GB	16GB	16GB	16GB	16GB	16GB	16GB	16GB	16GB	Best
192GB	32GB		32GB		32GB			32GB		32GB		32GB	Best
25000	32GB	32GB	32GB		32GB			32GB		32GB	32GB	32GB	Better
256GB	64GB		64GB							64GB		64GB	Better
204CD	32GB	32GB	32GB	32GB	32GB	32GB	32GB	32GB	32GB	32GB	32GB	32GB	Best
384GB	64GB		64GB		64GB			64GB		64GB		64GB	Best
512GB	64GB	64GB	64GB		64GB			64GB		64GB	64GB	64GB	Better
760.60	64GB	64GB	64GB	64GB	64GB	64GB	64GB	64GB	64GB	64GB	64GB	64GB	Best
768 GB	128GB		128GB		128GB			128GB		128GB		128GB	Best
1.5 TB	128GB	128GB	128GB	128GB	128GB	128GB	128GB	128GB	128GB	128GB	128GB	128GB	Best

HP Z8 G4 Workstation

System Technical Specifications

											Dual	Processo	r Configu	ration											
						C	PU 0						CPU 1												
System			Тор							om Slots					Тор							om Slots	·		Perf
Memor y	DIMM 1	DIMM 2	DIMM 3	DIMM 4	DIMM 5	DIMM 6	DIMM 7	DIMM 8	DIMM 9	DIMM 10	DIMM 11	DIMM 12	DIMM 1	DIMM 2	DIMM 3	DIMM 4	DIMM 5	DIMM 6	DIMM 7	DIMM 8	DIMM 9	DIMM 10	DIMM 11	DIMM 12	Ratin
16GB	8GB												8GB												Fair
32GB	8GB											8GB	8GB											8GB	Good
48GB	8GB		8GB		8GB								8GB		8GB		8GB								Bette
70GD	8GB		8GB							8GB		8GB	8GB		8GB							8GB		8GB	Bette
64GB	16GB											16GB	16GB											16GB	r
	8GB		8GB		8GB			8GB		8GB		8GB	8GB		8GB		8GB			8GB		8GB		8GB	Good Best
96GB	16GB		16GB		16GB			562		002		002	16GB		16GB		16GB					002		002	Bette
					TOOD												ТООВ								r Bette
128GB	16GB		16GB							16GB		16GB	16GB		16GB							16GB		16GB	r
	32GB											32GB	32GB											32GB	Good
	8GB	8GB	8GB	8GB	8GB	8GB	8GB	8GB	8GB	8GB	8GB	8GB	8GB	8GB	8GB	Best									
192GB	16GB		16GB		16GB			16GB		16GB		16GB	16GB		16GB		16GB			16GB		16GB		16GB	Best Bette
	32GB		32GB		32GB								32GB		32GB		32GB								r
256GB	32GB		32GB							32GB		32GB	32GB		32GB							32GB		32GB	Bette r
	64GB											64GB	64GB											64GB	Good
	16GB	16GB	16GB	16GB	16GB	16GB	16GB	16GB	16GB	16GB	16GB	16GB	16GB	16GB	16GB	Best									
384GB	32GB		32GB		32GB			32GB		32GB		32GB	32GB		32GB		32GB			32GB		32GB		32GB	Best
	64GB		64GB		64GB								64GB		64GB		64GB								Bette r
512GB	64GB		64GB							64GB		64GB	64GB		64GB							64GB		64GB	Bette
31200	32GB	32GB	32GB	32GB	32GB	32GB	32GB	32GB	32GB	32GB	32GB	32GB	32GB	32GB	32GB	Best									
768GB	64GB		64GB		64GB			64GB		64GB		64GB	64GB		64GB		64GB			64GB		64GB		64GB	Best
	128GB		128GB		128GB								128GB		128GB		128GB								Bette
	64GB	64GB	64GB		64GB			64GB		64GB	64GB	64GB	64GB	64GB	64GB		64GB			64GB		64GB	64GB	64GB	r Bette
1TB				6455		6465	5455		5455							5455		6465	6465		5.455				r
1.5TB	64GB	64GB	64GB	64GB	64GB	64GB	64GB	64GB	64GB	64GB	64GB	64GB	64GB	64GB	64GB	Best									
	128GB	l	128GB		128GB			128GB	l	128GB		128GB	128GB		128GB		128GB			128GB		128GB		128GB	Best



HP Z8 G4 Workstation

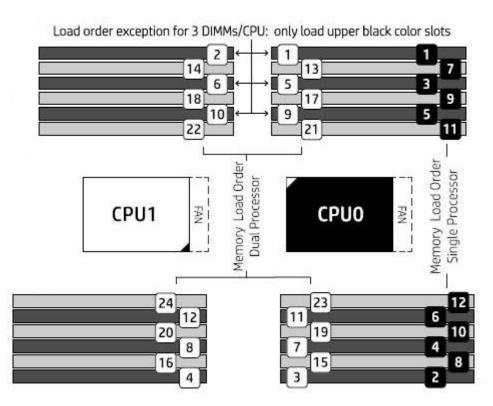
System Technical Specifications

3TB | 128GB |



Memory Loading Order:

Load Order for Single and Dual Processor Configuration



Maximum Memory

Supports up to 1.5TB with two processors, using RDIMMs Supports up to 3TB with two processors, using 3DS LR DIMMs*

*The 3TB configuration requires 128GB DIMMs which are no longer sold by HP

Memory Configuration (Supported)

Only ECC Registered DIMMs are supported.

- RDIMM (Registered), LR DIMM (Load Reduction) and 3DS LR DIMM (3D Stacked Load Reduced) memory cannot be mixed. All memory installed in the system must be either RDIMM, LR DIMM or 3DS LR DIMM.
- Do not install memory modules into memory slots if corresponding processor is not installed.
- Dual processor configurations with memory modules installed for only one processor is not supported.

Notes

For systems installed with Microsoft Windows 7 (Ultimate, Enterprise or Pro), the maximum accessible system memory is 192GB

- Sleep (S3 state) support:
- Sleep (S3 state) may not be supported with non-HP validated and qualified 64 GB LR DIMMs.
- Sleep (S3 state) not supported with 128 GB LR DIMMs

NVDIMM Memory

Intel® Optane™ DC Persistent Memory is available factory configured in the following capacities:

- 128GB (1x128GB) Single Processor Configuration
- 256GB (2x128GB) Single Processor Configuration
- 512GB (4x128GB) Dual Processor Configuration

- 1. Supported only with Xeon 82xx, 62xx, 52xx and 4215 processors.
 - a. Available as factory configured in Memory Mode or Storage Mode.
 - i. Microsoft Configured Memory Mode will be available in CQ1 2020
 - b. Systems configured with DCPMM memory will operate the memory subsystem at 2666 MT/s.
 - c. Operating System Support:
 - i. Windows 11 Pro for Workstations with all updates applied.
 - ii. Windows 10 Pro for Workstations v1903 or later with all updates applied.
 - iii. Linux OS support may be found in the Linux Hardware Support Matrix.
 - d. Detailed setup, security and support information may be found in the Intel® Optane™ DC Persistent Memory: Configuration and Setup on HP Z6 G4 and Z8 G4 Workstation white paper.
 - e. DCPMM solutions require additional DRAM memory to be included in the solution:
 - i. Systems configured with DCPMM in Memory Mode will include DRAM memory to be used as cache. The amount of included DRAM memory is based on an 8:1 DCPMM to DRAM capacity
 - ii. Systems configured with DCPMM in Storage Mode will require DRAM System Memory to be ordered separately.
 - iii. DCPMM Memory will report approximately 2% less than advertised capacity.
 - Total Memory (DCPMM + DRAM) per processor must be <= 1TB or 2TB per dual processor system.
 - i. Z8 G4 Note: "M" processors support a total memory limit < = 2TB per processors or 4TB per dual processor system
- 2. Option Kit available in CQ1-2020.
- 3. Requires 2nd processor option.

PCI Express Connectors Two PCIe Gen3 x16 with latch

Two PCIe Gen3 x16 with latch.

Enabled only with optional 2nd CPU is installed.

One PCIe Gen3 x8 open-ended connector.

- Enabled for One PCIe Gen2 x4 slot with 1 CPU
- Enabled for One PCIe Gen3 x8 with optional 2nd CPU installed

Two PCIe Gen3 x4 open-ended connectors

Supported Drive Interfaces

SATA 2 sSATA @6Gb/s, supports RAID 0, 1.

8 SATA @6Gb/s, supports RAID 0, 1, 5, 10.

Factory integrated Intel® SATA RAID is Microsoft Windows only.

External SATA (eSATA)* Supported on all SATA and sSATA ports configurable with optional eSATA* After-

Market Option cable kit)

* hot plug / hot swap not supported with eSATA

Factory Configured

RAID

SATA: RAID 0, 1, 10

Network Controller Integrated Intel I219LM Memory Integrated 3KB receive buffer and 3KB transmit buffer

Data rates supported: 10/100/1000 Mb/s

Compliance IEEE 802.1as/1588, 802.1p, 802.1Q, 802.3, 802.3ab, 802.3az, 802.3i

802.3u, 802.3x, 802.3z Up to 32 programmable filters

Bus architecture PCle 1.0 x1 and SMBus

UEFI and PXE Boot ROM support

Network transfer rates:

10BASE-T (half-duplex) 10 Mb/s 10BASE-T (full-duplex) 20 Mb/s



100BASE-TX (half-duplex) 100 Mb/s 100BASE-TX (full-duplex) 200 Mb/s 1000BASE-T (full-duplex) 2000 Mb/s

Management capabilities: WOL (All Power States, including Max Power Savings), auto MDI crossover, PXE, RSS, Advanced cable diagnostics, AMT 11.2x support.

vPro compliant

Integrated Intel X722

for 1GbE

Data rates supported: 1000 Mb/s

Compliance IEEE 802.1as/1588v2, 802.1p, 802.1Q, 802.3, 802.3ab, 802.3az,

802.3x

Up to 16 UDP/TCP programmable filters

Bus architecture: PCIe 3.0 UEFI and PXE Boot ROM support Intel iWARP Support (RDMA) Network transfer rates:

1000BASE-T (full-duplex) 2000 Mb/s

Management capabilities: WOL (Excluding Max Power Savings), auto MDI crossover, PXE, Quad Hash filtering, RSS, Advanced cable diagnostics

Integrated GraphicsNonePCI-X ConnectorsNonePCI Card GuideYes

Wake on LAN

Integrated Trusted Platform Module

Trusted Platform Module (TPM) 2.0 (Infineon SLB 9670)

Common Criteria EAL4+ Certified

FIPS 140-2 Certified (firmware v7.85)

TPM Certified products list:

Yes, both ports

https://trustedcomputinggroup.org/membership/certification/tpm-certified-products/

CG TPM Certified products list:

http://www.trustedcomputinggroup.org/certification/tpm-certified-products/

IEEE 1394 Connector(s) Front

Front None
Rear None
Internal None

USB Connector(s)

Front I/O Entry: 4 USB 3.1 Gen1 (Left-most Port has Charging Capability)

Front I/O Premium: 2x USB 3.1 Gen1, 2x USB 3.1 Gen2 Type-C™ (Left-most Port

has Charging Capability)

• Charging Ports provide 1.5 Amps @ 5 Volts

• Standard USB Type A Ports provide 900mA @ 5 Volts

• USB Type C Ports provide 3 Amps @ 5 Volts

Rear 6 USB 3.1 Gen1, Type A

Internal 1 USB 3.1 Gen1 available with a single 12-pin shrouded connector. This header

supports a USB Media Card reader.

1 USB 2.0 single-port header 1x USB 2.0 dual-port header

HD Integrated Audio Realtek ALC221

Flash ROM Yes

CPU Fan Header Two headers for CPU fans

Memory Fan Header Two headers

Chassis Fan Header One Rear Chassis Fan Header **Front PCI Fan Header** One Front and one Aux Fan Header



Front User Interface

Power Button; Power and HDD Activity LEDs; Power for USB Ports

Header

FIO Headset/Mic and Speaker Front Audio Header Yes

CMOS Battery Holder -

Lithium

Power Supply Headers Yes Clear Password Jumper Yes

Serial Port Yes, on rear panel

Parallel Port No Kevboard/Mouse Yes

1125W/1275W*/1450W* 1450W/1550W*/1700W* **Power Supply**

> 90% Efficient, Custom PSU 90% Efficient, Custom PSU (Wide-Ranging, Active PFC) (Wide-Ranging, Active PFC)

Operating Voltage 90-269 VAC 90-269 VAC

Range

100-127 VAC 118 VAC 100-127VAC 118 VAC Rated Voltage Range

200-240 VAC 200-240VAC

50-60 Hz 400 Hz 50-60Hz 400 Hz Rated Line Frequency Operating Line 47-66 Hz 393-407 Hz 47-66Hz 393-407 Hz

Frequency Range

Rated Input Current 12A @ 100-127 VAC 12A @ 118 VAC 16A @ 100-127 VAC 16A@ 118VAC

> 10A @ 200-240 VAC 10A @ 200-240 VAC

Heat Dissipation Typical = 2419 btu/hr Typical = 2970 btu/hr (Configuration and Max 1 = 4626 btu/hr Max 1 = 5962 btu/hr software dependent) Max 2 = 5001 btu/hrMax 2 = 6080 btu/hr Max 3 = 5560 btu/hrMax 3 = 6519 btu/hr

Power Supply Fan (2) Blowers variable speed (2) Blowers variable speed

Yes **ENERGY STAR** Yes

Oualified (Configuration dependent)

Power Supply 90% Efficient 90% Efficient

Efficiency The Z8 G4 1125W (1450W at 200V Input Voltage) The Z8 G4 1450W (1700W at 200V Input Voltage) power supply efficiency report can be found at this power supply efficiency report can be found at this link: link:

> https://plugloadsolutions.com/psu_reports/HP%20I https://plugloadsolutions.com/psu_reports/HP%20Inc nc DPS-

1125BB%20A_1125W_ECOS%204825_Report.pdf 1450AB%20A_1450W_ECOS%204826_Report.pdf

FEMP Standby Power Yes Yes

Compliant @115V (<2W in S5 - Power

Off)

230V

EuP Compliant @ Yes Yes

(<0.5 W in S5 - Power

Off)

CECP Compliant @ Yes; Configuration dependent Yes; Configuration dependent

220V



(<4W in S3 - Suspend

to RAM)

Power Consumption TBD TBD

in sleep mode (as defined by ENERGY STAR) -Suspend to RAM (S3) (Instantly Available

PC)

Built-in Self-Test LEDYesYesSurge Tolerant FullYesYes

Ranging Power

Supply (withstands power

surges up to 2000V)

*Input voltage restriction

NOTE: The 1125W (1450W at 200V Input Voltage) power supply can also supply 1275W of output power when the input voltage is greater than 105V. If the input voltage is less than 105V, but greater than 90V for any reason, the maximum power that can be drawn is 1125W. An uninterruptible power supply (UPS) is highly recommended if 1275W output power is desired.

The 1125W Power Supply can also supply 1450W of output power when the input voltage is greater than 180V under all conditions.

NOTE: The 1450W (1700W at 200V Input Voltage) power supply can also supply 1550W of output power when the input voltage is greater than 105V. If the input voltage is less than 105V, but greater than 90V for any reason, the maximum power that can be drawn is 1450W. An uninterruptible power supply (UPS) is highly recommended if 1550W output power is desired.

The 1450W Power Supply can also supply 1700W of output power when the input voltage is greater than 180V under all conditions.

AUX IN (audio) No Clear CMOS Button Yes Multibay Header No

Integrated Gigabit Yes, dual port.

Ethernet

Access Panel No Solenoid Lock Header

Solenoid Lock Header

Access Panel Yes.

Intrusion Sensor

Header

Memory Fan Connector Yes, as part of Front UI (Control Panel) cable header

Yes, blind-mate

System Technical Specifications

System Configurations

Example Z8 G4	Processor Info	1x Intel Xeon	3106 1.7 2133	8C 85 1stCPU				
Configuration #1	Memory Info	16GB DDR4-2	:666 (2x8GB) Re	egRAM CPU1				
	Graphics Info	1x NVIDIA Qu	adro P600					
	Disks/Optical/Floppy	1x 256GB SA	TA 1st SSD /1x [OVD-ROM SAT	Ά			
	Power Supply	1125W 90% (Custom PSU					
	Other	-						
		115	5 VAC	230	VAC	100	VAC	
F		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Enabled	
Energy Consumption	Windows Idle (S0)	7	5.4	74	1.8	75	5.7	
	Windows Busy Typ(S0)	12	2.04	11	1.9	113.6		
	Windows Busy Max (S0)	12	125.4		124.6		6.6	
	Sleep (S3)	6.22	6.26	6.26	6.26	6.33	6.25	
	Off (S5)	4.23	4.19	4.19 4.16		4.13	4.12	
	Zero Power Mode (ErP)	0	.31	0.	40	0.29		
		115	5 VAC	230	VAC	100 VAC		
Heat Dissipation		LAN Enabled	LAN Disabled	LAN Enabled	LAN Enabled	LAN Disabled	LAN Enabled	
(Btu/hr)	Windows Idle (S0)	25	57.5	25	5.3	25	8.5	
	Windows Busy Typ(S0)	41	16.4	38	2.0	38	7.6	
	Windows Busy Max (S0)	42	27.9	42	5.1	43	32.0	
	Sleep (S3)	21.2	21.1	21.3	21.2	21.6	21.3	
	Off (S5)	14.4	14.0	14.3	14.2	14.1	14.1	
	Zero Power Mode (ErP)	1	.04	1.	38	0.9	99	

Example Z8 G4	Processor Info	2x Intel Xeon 4114 2.2 2400 10C 85 1stCPU									
Configuration #2	Memory Info	48GB DDR4-2	666 (6x8GB) R	egRAM CPU2							
	Graphics Info	1x NVIDIA Qua	adro P2000								
	Disks/Optical/Floppy	4x 512GB SAT	A 1st SSD /1x	DVD-ROM SAT	Α						
	Power Supply	1125W 90% C	ustom PSU								
	Other	-									
		115	VAC	230	VAC	100	VAC				
F		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Enabled				
Energy Consumption	Windows Idle (S0)	10)5.2	10	3.3	102.5					
	Windows Busy Typ(S0)	25	57.4	24	6.3	26	0.9				
	Windows Busy Max (S0)	29	06.2	28	9.9	297.6					
	Sleep (S3)	8.46	8.35	8.57	8.45	8.58	8.57				
	Off (S5)	4.15	4.14	4.31	4.19	4.21	4.15				
	Zero Power Mode (ErP)	0	.31	0.	40	0.	29				
		115	5 VAC	230	VAC	100 VAC					
Heat Dissipation		LAN Enabled	LAN Disabled	LAN Enabled	LAN Enabled	LAN Disabled	LAN Enabled				
(Btu/hr)	Windows Idle (S0)	35	9.0	35	2.5	34	9.8				
	Windows Busy Typ(S0)	87	'8.3	84	0.5	890.2					



System Technical Specifications

Windows Busy Max (S0)	1010.7		98	9.1	1015.6	
Sleep (S3)	28.8	28.5	29.2	28.8	29.2	29.2
Off (S5)	14.1	14.1	14.6	14.2	14.3	14.1
Zero Power Mode (ErP)	1	.04	1.	36	0.	99

Example Z8 G4	Processor Info	2x Intel Xeon	5120 2.2 2400	14C 105 1stC	PU		
Configuration #3	Memory Info	96GB DDR4-2	2666 (12x8GB) F	RegRAM CPU2			
	Graphics Info	1x NVIDIA Qu	adro P4000				
	Disks/Optical/Floppy	4x 2TB 7200	RPM SATA 1st F	IDD /1x DVDR	W SATA		
	Power Supply	1125W 90% Custom PSU					
	Other	-					
		115 VAC 230 VAC 100 VAC					VAC
		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Enabled
Energy Consumption	Windows Idle (S0)	12	25.7	12	3.6	125.8	
	Windows Busy Typ(S0)	340.7 332		2.9	343.7		
	Windows Busy Max (S0)	41	17.1	41	1.8	426.1	
	Sleep (S3)	9.28	9.10	9.24	9.15	9.49	9.26
	Off (S5)	4.15	4.14	4.32	4.10	4.21	4.16
	Zero Power Mode (ErP)	0	.31	0.	41	0.	30
		115	115 VAC 230 VAC		100 VAC		
		LAN Enabled	LAN Disabled	LAN Enabled	LAN Enabled	LAN Disabled	LAN Enabled
Heat Dissipation	Windows Idle (S0)	42	29.3	422.0		429.5	
(Btu/hr)	Windows Busy Typ(S0)	1162.7 1423.4		1136.0		1172.9	
	Windows Busy Max (S0)			140	1405.3		1453.9
	Sleep (S3)	31.6	31.0	31.5	31.2	32.4	31.5
	Off (S5)	14.1	14.1	14.7	13.9	14.3	14.2
	Zero Power Mode (ErP)	1	.05	1.	38	1.	03

Example Z8 G4	Processor Info	2x Intel Xeon 6152 2.1 2666 22C 140 CPU						
Configuration #4	Memory Info	192GB DDR4-2666 (24x8GB) RegRAM CPU						
	Graphics Info	2x NVIDIA Qua	dro P5000					
	Disks/Optical/Floppy	6x 1 TB SATA	SSD /1x DVD	RW SATA				
	Power Supply	1125W 90% Custom PSU						
	Other	-						
		115 VAC 230 VAC 100 VA			VAC			
F		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Enabled	
Energy Consumption	Windows Idle (S0)	161.1		157.8		160.4		
	Windows Busy Typ(S0)	524.7		500.7		496.1		
	Windows Busy Max (S0)	644	4.2	62	4.2	652.7		
	Sleep (S3)	10.3	10.2	10.2	10.1	10.1	10.1	
	Off (S5)	4.14	4.01	4.19	4.19	4.16	4.15	
	Zero Power Mode (ErP)	0.3	31	0.41		0.31		



System Technical Specifications

		115 VAC		230 VAC		100 VAC	
Heat Dissipation		LAN Enabled	LAN Disabled	LAN Enabled	LAN Enabled	LAN Disabled	LAN Enabled
(Btu/hr)	Windows Idle (S0)	549.6		538.4		547.5	
	Windows Busy Typ(S0)	1790.4		1708.6		1692.6	
	Windows Busy Max (S0)	2198.1		2129.8		2227.0	
	Sleep (S3)	35.3	34.9	35.0	34.7	34.5	134.3
	Off (S5)	14.1	13.6	14.3	14.3	14.2	14.1
	Zero Power Mode (ErP)	1.06		1.39		1.04	

Example Z8 G4	Processor Info	2x Intel Xeon	6136 3.0 2660	6 12C 150 CPU			
Configuration #5	Memory Info			GB) RegRAM CF			
	Graphics Info	2x NVIDIA Qua		b) negram rei	<u> </u>		
		1					
	Disks/Optical/Floppy	HP Z Turbo Q	uad Pro 4x1TE	3 + 4x 1 TB SA	TA SSD /1x D\	JDRW SATA	
	Power Supply	1450W 90% C	ustom PSU				
	Other	-					
		115 VAC 230 VAC 100 VAC					
		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Enabled
Energy Consumption	Windows Idle (S0)	194.0		192.6		197.0	
	Windows Busy Typ(S0)	640.2		622.0		647.0	
	Windows Busy Max (S0)		788.0 761.3		1.3	800.6	
	Sleep (S3)	21.1	19.7	19.7	18.8	21.3	19.8
	Off (S5)	4.24	4.22	4.53	4.51	4.24	4.21
		115	VAC	230	VAC	100	VAC
Heat Dissipation		LAN Enabled	LAN Disabled	LAN Enabled	LAN Enabled	LAN Disabled	LAN Enabled
(Btu/hr)	Windows Idle (S0)	662	2.1	657.2		672.3	
	Windows Busy Typ(S0)	218	4.3	2122.3		2207.7	
	Windows Busy Max (S0)		8.8	259	7.8	273	31.7
	Sleep (S3)	72.3	67.5	67.5	64.1	72.6	67.7
	Off (S5)	14.4	14.4	15.4	15.4	14.4	14.3

NOTE: Power consumption measurements do not take advantage of the Intel Turbo Boost Technology. As a result, power consumption measurements may be higher.

DECLARED NOISE EMISSIONS

System Configuration Processor Info		2-Intel® Xeon® Gold 6134 processor 3.2GHz 8C CPU
(Entry level)	Memory Info	96GB (12x8GB) DDR4-2666 ECC Memory RDIMMs
	Graphics Info	1-NVIDIA® Quadro® P400 2GB
	Disks/Optical	1-500GB SATA 7200RPM 3.5" HDD / 1-HP 9.5mm Slim Blu Ray Disc Writer
	Power Supply	1125 W

Declared Noise Emissions (in accordance with ISO		Sound Power (LWAd, bels)	Deskside Sound Pressure (LpAm, decibels)
7779 and ISO 9296)	Idle	3.6	19



System Technical Specifications

Hard drive Operating (random reads)	3.7	19
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System Configuration	Processor Info	2-Intel® Xeon® Gold 6146 processor 3.2GHz 12C CPU
(Mid-range)	Memory Info	384GB (24x16GB) DDR4-2666 ECC Memory RDIMMs
	Graphics Info	1-NVIDIA® Quadro® P6000 24GB
Disks/Optical		2-300GB 12Gb/s 15KRPM SAS HDD / 1-HP 9.5mm Slim Blu Ray Disc Writer
	Power Supply	1450 W

Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)		Sound Power (LWAd, bels)	Deskside Sound Pressure (LpAm, decibels)	
	Idle	3.6	20	
	Hard drive Operating (random reads)	3.8	23	

ENVIRONMENTAL DATA

Environmental Temperature

Requirements

Operating: 5° to 35° C (40° to 95° F) Non-operating: -40° to 60° C (-40° to 140° F)

Humidity Operating: 8% to 85% RH, non-condensing

Non-operating: 8% to 90% RH, non-condensing

Maximum Altitude Operating: 3,048 m (10,000 feet)

Non-operating: 9,144 m (30,000 feet)

Dynamic (new) Shock

> Operating: ½-sine: 40g, 2-3ms (~62 cm/sec) Non-operating: 1/2-sine: 160 cm/s, 2-3ms (~105g)

square: 422 cm/s, 20q

NOTE: Values represent individual shock events and do not indicate

repetitive shock events.

Vibration

Operating random: 0.5g (rms), 5-300 Hz, up to 0.0025g2/Hz Non-operating random: 2.0g (rms), 5-500 Hz, up to 0.0150 g²/Hz

NOTE: Values do not indicate continuous vibration.

Cooling Above 1524 m (5,000 feet) altitude, the maximum operating temperature is

reduced by 1°C (1.8°F) for every 305 m (1,000 feet) increase in elevation, up

to 3048 m (10,000 feet)

Physical Security and Serviceability

Access Panel Tool-less

Includes system board and memory information.

Optical Drive Tool-less, 2nd Optical Drive requires a 5.25" bay carrier

Tool-less **Hard Drives Expansion Cards** Tool-less Tool-less **Processor Socket**



System Technical Specifications

Blue User Touch Points Yes, on tool-free internal chassis components.

Color-coordinated Cables Yes

and Connectors

Memory Tool-less

System Board Tool-less, retained by Front Card Guide and Top Memory Fan Holder

Dual Color Power and HD No **LED on Front of Computer Configuration Record SW** Yes

Over-Temp Warning on

Yes. Temp-Caution and Temp Critical are provide via the WMI interface. Tools like the HPPA can display

Screen the Critical and Caution state.

Restore CD/DVD Set Restores the computer to its original factory shipping image; can be obtained via HP Support.

Dual Function Front Power Yes, causes a fail-safe power off when held for 4 seconds

Switch

Padlock Support No

Cable Lock Support Yes, Kensington Cable Lock (optional): Prevents entire system theft only. 3mm x 7mm slot at rear of

system No

Universal Chassis Clamp

Lock Support

Solenoid Lock and Hood No

Sensor

Rear Port Control Cover No

Serial, USB, Yes. USB disablement zones are Front, Rear and Internal

Audio, Network, Enable/Disable Port

Control

Removable Media No

Write/Boot Control

Power-On Password Yes, prevents an unauthorized person from booting up the workstation

Setup Password Yes, prevents an unauthorized person from changing the workstation configuration

3.3V Aux Power LED on No

System PCA

NIC LEDs (integrated) Yes

(Green & Amber)

CPUs and Heatsinks A torx driver (T30) is needed to remove the heatsink(s). CPU attached to heatsink via tool-less clip

Power Supply Diagnostic

LED

Front Power Button Yes

Front Power LED Yes, white (normal), red (fault)

Yes

Front Hard Drive Activity Yes, white

LED

Front ODD Activity LED Yes

Internal Speaker Yes

System/Emergency ROM

Flash Recovery

Recovers corrupted system BIOS

Cooling Solutions Air cooled forced convection **Power Supply Fans** 2x – Dual Side Inlet Blowers

CPU Heatsink Fan 80mm x 25mm 5-wire PWM for each CPU

Chassis Fan Rear: 120mm x 38mm

Front: 120mm x 25mm (PCIe zone)



Memory Heatsink Fan Front 92mm x 25mm (upper memory bank); Front 80mm x 25mm (lower memory bank)

HP PC Hardware Diagnostics UEFI

HP PC Hardware Diagnostics (UEFI) enables hardware level testing outside the operating system on many components. The diagnostics can be invoked by pressing ESC then F2 upon the PC reboot, and is

available as a download from HP Support.

Access Panel Key Lock Yes, prevents removal of the access panel and all internal components including optical and storage

devices

ACPI-Ready Hardware Advanced Configuration and Power Management Interface (ACPI).

Allows the system to wake from a low-power mode.

 Controls system power consumption, making it possible to place individual cards and peripherals in a low-power or powered-off state without affecting other elements of the system

Trusted Platform Module Yes

Chip

Integrated Chassis

Handles

Yes, front and rear

rianutes

Power Supply Tool-less, rear access direct-connect (blind-mate)

PCIe Card Retention Yes, tool-less Rear (all)

Middle (full-height cards)

Front (full-length cards with extenders)

Flash ROM Yes.SPI ROM

Diagnostic Power Switch

LED on board

Clear Password Jumper Yes
Clear CMOS Button Yes
CMOS Battery Holder Yes
DIMM Connectors Yes

BIOS

BIOS 32-bit Services Standard BIOS 32-bit Service Directory Proposal v0.4

BIOS supports 32 and 64-bit Operating systems.

PCI 3.0 Support Full BIOS support for PCI Express through industry standard interfaces.

ATAPI ATAPI Removable Media Device BIOS Specification Version 1.0.

BIOS Boot Specification v1.01.

Yes

WMI Support WMI is Microsoft's implementation of Web-Based Enterprise Management (WBEM) for Windows. WMI is

fully compliant with the Distributed Management Task Force (DMTF) Common Information Model (CIM)

and WBEM specifications.

BIOS Boot Spec 1.01+

Provides more control over how and from what devices the workstation will boot.

BIOS Power On Users can define a specific date and time for the system to power on.

ROM Based Computer Setup Utility (F10) Review and customize system configuration settings controlled by the BIOS.

System/Emergency ROM Recov Flash Recovery with Video

Recovers system BIOS in corrupted Flash ROM.

Replicated Setup Saves BIOS settings to USB flash device in human readable file (HpSetup.txt).

BiosConfigurationUtility.exe utility can then replicate these settings on machines being deployed

without entering Computer Configuration Utility (F10 Setup).

SMBIOS System Management BIOS 2.8, for system management information.

Boot Control Disables the ability to boot from removable media on supported devices.



System Technical Specifications

Memory Change Alert Thermal Alert

Alerts management console if memory is removed or changed. Monitors the temperature state within the chassis. Three modes:

• NORMAL - normal temperature ranges.

ALERTED - excessive temperatures are detected. Raises a flag so action can be taken to avoid

shutdown or provide for a smoother system shutdown.

• SHUTDOWN - excessive temperatures are encountered. Automatically shuts down the computer

without warning before hardware component damage occurs.

Remote ROM Flash **ACPI (Advanced**

Provides secure, fail-safe ROM image management from a central network console. Allows the system to enter and resume from low power modes (sleep states).

Configuration and Power Management Interface)

Enables an operating system to control system power consumption based on the dynamic workload. Makes it possible to place individual cards and peripherals in a low-power or powered-off state without

affecting other elements of the system.

Supports ACPI 5.0 for full compatibility with 64-bit operating systems.

Ownership Tag Remote Wakeup/Remote

A user-defined string stored in non-volatile memory that is displayed in the BIOS splash screen.

Shutdown

System administrators can power on, restart, and power off a client computer from a remote location.

Instantly Available PC (Suspend to RAM - ACPI sleep state S3)

Allows for very low power consumption with quick resume time.

Remote System

Installation via F12 (PXE

Allows a new or existing system to boot over the network and download software, including the

operating system.

2.1) (Remote Boot from Server)

ROM revision levels

Reports the system BIOS revision level in Computer Configuration Utility (F10 Setup). Version is

available through an industry standard interface (SMBIOS and WMI) so that management SW

applications can use and report this information.

System board revision

level

Allows management SW to read revision level of the system board. Revision level is digitally encoded into the HW and cannot be modified. Assesses system health at boot time with selectable levels of testing.

Start-up Diagnostics (Power-on Self-Test)

Auto Setup when new

hardware installed

System automatically detects addition of new hardware.

Keyboard-less Operation

The system can be booted without a keyboard.

Localized ROM Setup

Common BIOS image supports System Configuration Utility (F10 Setup) menus in 14 languages with

local keyboard mappings.

Asset Tag

The user or MIS to set a unique tag string in non-volatile memory.

Per-slot Control Adaptive Cooling **Pre-boot Diagnostics** Allows I/O slot parameters (option ROM enable/disable, bus latency) to be configured individually. Control parameters are set according to detected hardware configuration for optimal acoustics.

(Pre-video) critical errors are reported via beeps and blinks on the power LED.

Industry Standard Specification Support

Industry Standard Revision Supported by the BIOS

UEFI Specification Revision 2.6

ACPI Advanced Configuration and Power Management Interface, Version 5.0 ATA (IDE) AT Attachment 6 with Packet Interface (ATA/ATAPI-6), Revision 3b CD Boot "El Torito" Bootable CD-ROM Format Specification Version 1.0

EDD - Enhanced Disk Drive Specification Version 1.1

- BIOS Enhanced Disk Drive Specification Version 3.0

EHCI Enhanced Host Controller Interface for Universal Serial Bus. Revision 1.0

PCI PCI Local Bus Specification, Revision 2.3

> PCI Power Management Specification, Revision 1.1 PCI Firmware Specification, Revision 3.0, Draft .7



System Technical Specifications

PCI Express Base Specification, Revision 2.0 **PCI Express**

PCI Express Base Specification, Revision 3.0

PMM POST Memory Manager Specification, Version 1.01

Serial ATA Specification, Revision 1.0a **SATA**

> Serial ATA 3 Gb/s: Serial ATA Specification, Revision 2.5 Serial ATA 6 Gb/s: Serial ATA Specification, Revision 3.0

SPD PC SDRAM Serial Presence Detect (SPD) Specification, Revision 1.2B

Trusted Computing Group TPM Specification Version 2.0 (Infineon SLB 9670). **TPM**

Common Criteria EAL4+ certified.

FIPS 140-2 Certification TCG TPM Certified products list:

http://www.trustedcomputinggroup.org/certification/tpm-certified-products/

Universal Host Controller Interface Design Guide, Revision 1.1 **UHCI**

USB Universal Serial Bus Revision 1.1 Specification

Universal Serial Bus Revision 2.0 Specification

Universal Serial Bus Revision 3.1 Specification

SMBIOS System Management BIOS Reference Specification, Version 2.8

External BIOS simulator found at: http://csrsml.itcs.hp.com/

Social and Environmental Responsibility

Eco-Label Certifications & This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks: **Declarations**

- ENERGY STAR® (energy-saving features available on selected configurations-Windows only)
- US Federal Energy Management Program (FEMP)
- **China Energy Conservation Program**
- The ECO declaration (TED)
- TCO Certified configurations available*

*TCO Certified configurations available when ENERGY STAR configurations are selected with a USB Type-C[®] connector. ENERGY STAR available with a combination of high-performance CPU's, highperformance GPU's and select memory configurations.

The Z8 G4 is registered EPEAT® Silver in the US and Canada. EPEAT® registration varies by country. See http://www.epeat.net for registration status by country. Search keyword generator on HP's 3rd party option store for solar generator accessories at http://www.hp.com/go/options

The battery in this product complies with EU Directive 2006/66/EC

Battery size: CR2032 (coin cell)

Battery mass: 3q

Battery type: Lithium Metal

The battery in this product does not contain:

- Mercury greater than 5ppm by weight
- Cadmium greater than 10ppm by weight
- Lead greater than 40ppm by weight

Restricted Material Usage This product meets the material restrictions specified in HP's General Specification for the Environment.



Batteries

System Technical Specifications

HP Inc. is committed to compliance with all applicable environmental laws and regulations, including the European Union Restriction of Hazardous Substances (RoHS) Directive. HP's goal is to exceed compliance obligations by meeting the requirements of the RoHS Directive on a worldwide basis

Low Halogen Statement

This product is low halogen except for power cords, external cables and peripherals. The following customer-configurable internal components may not be low-halogen: 3 1/2" SAS HDDs. Service parts obtained after purchase may not be low halogen.

(Note: optional low-halogen power cables are available for some countries in Europe)

and Recycling

End-of-Life Management HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner. This product is greater than 90% recyclable by weight when properly disposed of at end of life.

HP Inc. Corporate Environmental Information Sustainability Report

For more information about HP's commitment to the environment:

Eco-label certifications:

http://www.hp.com/hpinfo/globalcitizenship/environment/productdesign/ecolabels.html

ISO 14001 certificate:

http://www.hp.com/hpinfo/globalcitizenship/environment/operations/envmanagement.html

Additional Information

- This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive - 2002/96/EC. Product Disassembly Instructions
- Plastic parts weighing over 25 grams used in the product are marked per ISO 11469 and IS01043.
- This product is >90% recycle-able when properly disposed of at end of life.

Packaging

HP Workstation product packaging meets the HP's General Specification for the Environment

- Does not contain restricted substances listed in HP Standard 011-1 General Specification for the Environment
- Does not contain ozone-depleting substances (ODS)
- Does not contain heavy metals (lead, mercury, cadmium or hexavalent chromium) in excess of 100 ppm sum total for all heavy metals listed
- Maximizes the use of post-consumer recycled content materials in packaging materials
- All packaging material is recyclable
- All packaging material is designed for ease of disassembly
- Reduced size and weight of packages to improve transportation fuel efficiency
- Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards formatting
- A multi-unit eco packaging option is available to institutional customers that uses less packaging material or has a lower volume footprint than conventional single-unit packaging. Please contact your sales representative for additional details.

Packaging Materials

Internal **External** Cushions and plastic bags made of low density polyethylene (LDPE).

Outer carton, accessories carton, and insert made of corrugated paper board.

Manageability

Industry Standard Specifications

This product meets the following industry standard specifications for manageability functionality:

DASH 1.1 (via Intel® LAN on motherboard)

Intel® Active Management Intel® Active Management Technology (AMT) 11.2x Technology (AMT)



System Technical Specifications

An advanced set of remote management features and functionality providing IT administrators the latest and most effective tools to remotely discover, heal, and protect networked client systems regardless of the system's health or power state. AMT 11.2x includes the following advanced management functions:

- Power Management (on, off, reset, graceful shutdown, sleep and hibernate)
 - Support in Max Power Savings (Shutdown and Hibernate Modes)
- Hardware Inventory (includes BIOS and firmware revisions)
- Hardware Alerting
- **Agent Presence**
- **System Defense Filters**
- Serial Over LAN (SOL)
- **USB Redirect (Media Redirection)**
- ME Wake-on-LAN (WOL), even with Maximum Power Savings Enabled
- DASH 1.1 compliance
- **IPv6** Support
- Fast Call for Help a client inside or outside the firewall may initiate a call for help via BIOS screen, periodic connections, or alert triggered connection
- Remote Scheduled Maintenance pre-schedule when the system connects to the IT or service provider console for maintenance.
- Remote Alerts automatically alert IT or service provider if issues arise
- Access Monitor Provides oversight into Intel® AMT actions to support security requirements
- PC Alarm Clock
- Microsoft NAP Support
- Host Base set-up and configuration
- Management Engine (ME) firmware roll back
- Local Time Sync to UTC
- Remote Memory Dump Command Creates memory dump for debug

Intel® vPro™ Technology The HP Z8 G4 Workstation supports Intel® vPro™ technology when configured as outlined below:

- Intel® Xeon® processor E5-1600 v5 or E5-2600 v5 product family featuring Intel® vPro™ Technology
- Intel® C622 chipset
- Intel® I219LM GbE LAN

Remote Manageability Software Solutions

The HP Z8 G4 Workstation is supported on the following remote manageability software consoles:

- LANDesk Management Suite (HP recommended solution)
- Microsoft System Center Configuration Manager
- **HP Client Automation Enterprise**

For questions or support for manageability needs, please visit http://www.hp.com/go/clientmanagement

Service, Support, and Warranty

System Software Manager For questions or support for SSM, please visit: http://www.hp.com/go/ssm

On-site Warranty and Service (Note 1): Three-years, limited warranty and service offering delivers onsite, next business-day (Note 2) service for parts and labor and includes free telephone support (Note 3) 8am - 5pm. Global coverage (Note 2) ensures that any product purchased in one country and transferred to another, non-restricted country will remain fully covered under the original warranty and service offering. 24/7 operation will not void the HP warranty.

NOTE 1: Terms and conditions may vary by country. Certain restrictions and exclusions apply.

NOTE 2: On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.

NOTE 3: Technical telephone support applies only to HP-configured, HP and HP-qualified, third-party



System Technical Specifications

hardware and software. Toll-free calling and 24x7 support service may not be available in some countries.

HP Care Pack Services are extended service contracts that go beyond the standard limited warranties. Service starts from date of hardware purchase. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: http://www.hp.com/go/lookuptool. Additional HP Care Pack Services information by product is available at: http://www.hp.com/hps/carepack. Service levels and response times for HP Care Packs may vary depending on your geographic location. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

Product Change Notification

- Program to proactively communicate Product Change Notifications (PCNs) and Customer Advisories by email to customers, based on a user-defined profile.
- PCNs provide advance notification of hardware and software changes to be implemented in the factory providing time to plan for transition.
- Customer Advisories provide concise, effective problem resolution, greatly reducing the need to call technical support.

Stable & Consistent Offerings

Global Series SKUs	this breakthrough platfo Consistent Offerings are designed and tested to v components and their co section.	nt to hardware, software, and solution innovation, HP is proud to introduce orm configuration stability to HP Workstation customers. HP Stable & built on the foundation of a carefully chosen set of hardware and software work with all HP Z Workstation platforms through their end of life. These orresponding HP Workstation platform compatibility are outlined in this	
Stable & Consistent Offerings	HP Stable & Consistent Offerings are available worldwide to all HP Workstation customers-no special programs, no additional cost-no kidding. Simply select your hardware and software components when you customize your HP Workstation and be assured that you'll be able to buy that same configuration throughout the lifecycle of the product.		
Processors	Product #	Offering	
	2DL76AV	Intel® Xeon® Gold 6128 processor	
	2DL77AV / 1XM69AA	Intel® Xeon® Gold 6128 2 nd processor	
	2DL66AV	Intel® Xeon® Silver 4114 processor	
	2DL67AV / 1XM74AA	Intel® Xeon® Silver 4114 2 nd processor	
	2DL62AV	Intel® Xeon® Silver 4108 processor	
	2DL63AV / 1XM76AA	Intel® Xeon® Silver 4108 2 nd processor	
Hard Drives	Product #	Offering	
	Z5J60AV / LQ037AA	1TB SATA 7200 RPM 3.5" HDD	
Graphics	Product #	Offering	
	2TF08AA	AMD Radeon™ Pro WX 3100 4GB Graphics	
Memory	Product #	Offering	
	TBD	TBD	



Optical and Removable

Storage

Product #

TBD

Offering

TBD

Technical Specifications - Processors

Intel® Xeon® Platinum 8260L processor

Intel® Xeon® Gold 6258R processor

Intel® Xeon® Gold 6248R processor

Intel® Xeon® Gold 6246R processor

Intel® Xeon® Gold 6244 processor

Intel® Xeon® Gold 6242R processor

Intel® Xeon® Gold 6242 processor

Intel® Xeon® Gold 6240R processor

Intel® Xeon® Gold 6240 processor

Intel® Xeon® Gold 6238R processor

Intel® Xeon® Gold 6230R processor

Intel® Xeon® Gold 6226R processor

Intel® Xeon® Gold 6226 processor

Intel® Xeon® Gold 6136 processor

Intel® Xeon® Gold 6128 processor

Intel® Xeon® Gold 5222 processor

Intel® Xeon® Gold 5220R processor

Intel® Xeon® Gold 5218R processor

Intel® Xeon® Gold 5218 processor

Intel® Xeon® Gold 5215 processor

Intel® Xeon® Gold 5118 processor

Intel® Xeon® Gold 4216 processor

Intel® Xeon® Gold 4215R processor

Intel® Xeon® Gold 4214R processor

Intel® Xeon® Gold 4214 processor

Intel® Xeon® Gold 4210R processor

Intel® Xeon® Gold 4210 processor

Intel® Xeon® Gold 4208 processor

Intel® Xeon® Silver 4114 processor

Intel® Xeon® Silver 4108 processor

Intel® Xeon® Bronze 3206R processor

Intel® Xeon® Bronze 3204 processor



Technical Specifications - Hard Drives

STORAGE/HARD DRIVES

HP SAS (Serial Attached SCSI) Hard Drives for HP

Workstations

HP 300GB SAS 15K SFF

HDD

Capacity300GBHeight5.9 in; 15 cm

Width Media Diameter 3.5 in; 8.9 cm

Interface 12Gb/s SAS

Synchronous Transfer Up to 1200 MB/s (SAS single port)*

Rate (Maximum)

Buffer 128MB

Seek Time (typical reads, Average 2.0ms *

includes controller overhead, including

settling)

Rotational Speed 15K rpm

Operating Temperature 41° to 131° F (5° to 55° C)

*Actual performance may vary.

Technical Specifications - Hard Drives

SATA (Serial ATA) Hard Drives for HP Workstations 500GB SATA 7200 rpm 6Gb/s 3.5" HDD Capacity500GBHeight1 in; 2.54 cmWidthMedia Diamet

Media Diameter 3.5 in; 8.9 cm
Physical Size 4 in; 10.17 cm

Interface Serial ATA (6.0Gb/s), NCQ enabled

Synchronous Transfer Up to 600MB/s*

Rate (Maximum)

Buffer 16MB

Seek Time (typical reads,
includes controller
overhead, including
settling)Single Track
Average2 ms*Average
Full Stroke11 ms*21 ms*

Rotational Speed 7,200 rpm Logical Blocks 976,773,168

Operating Temperature 41° to 131° F (5° to 55° C)

1TB SATA 7200 rpm 6Gb/s 3.5" HDD Capacity 1TB

Height 1 in; 2.54 cm

Width Media Diameter 3.5 in; 8.9 cm
Physical Size 4 in; 10.17 cm

Up to 600 MB/s*

Interface Serial ATA (6.0Gb/s), NCQ enabled

Synchronous Transfer

Rate (Maximum)

Buffer 64MB Cache Adaptive

Seek Time (typical reads,
includes controller
overhead, including
settling)Single Track
Average2 ms*11 ms*
Full Stroke21 ms*

Rotational Speed 7,200 rpm

Operating Temperature 41° to 131° F (5° to 55° C)

2.0TB SATA 7200 rpm 6Gb/s 3.5" HDD CMR

 Capacity
 2.0TB

 Height
 1 in; 2.54 cm

Width Media Diameter 3.5 in; 8.9 cm

Up to 600 MB/s*

Physical Size 4 in; 10.17 cm

Interface Serial ATA (6.0 Gb/s), NCQ Enabled

Synchronous Transfer

Rate (Maximum)

Buffer 64MB

Seek Time (typical reads, includes controller overhead, includingSingle Track1.0 ms*Average11 ms*Full Stroke18 ms*

settling)

Rotational Speed 7,200 rpm



^{*}Actual performance may vary.

^{*}Actual performance may vary.

Technical Specifications - Hard Drives

Logical Blocks 3,907,029,168

Operating Temperature 41° to 131° F (5° to 55° C)

*Actual performance may vary.

2.0TB SATA 7200 rpm 6Gb/s 3.5" HDD SMR

Capacity 2.0TB
Height 1 in; 2.02 cm

Width Media Diameter 3.5 in; 8.9 cm

Up to 600 MB/s*

Physical Size 4 in; 10.16 cm

Interface Serial ATA (6.0 Gb/s), NCQ Enabled

Synchronous Transfer

Rate (Maximum)

DECME

Buffer 256MB

Seek Time (typical reads,
includes controller
overhead, including
cottling)Single Track
Average1.2 ms*Full Stroke21 ms*

settling)

Rotational Speed 7,200 rpm **Logical Blocks** 3,907,029,168

Operating Temperature 41° to 140° F (5° to 60° C)

1TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class) Capacity 1TB
Protocol SATA
Form Factor 3.5"
Controller AHCI
Reliability (MTBF) 2.0M hours
Rated Power On Hours 8760/yr
Annualized Failure Rate <0.62%

(based on Rated POH)

Rated for 24/7/365 YES

operation
Physical Size (Height) 1 in; 2.54 cm

Physical Size (Height) 1 in; 2.54 cm
Physical Size (Width) 4 in; 10.17 cm
Media Diameter 3.5 in; 8.9 cm

Interface Serial ATA (6Gb/s), NCQ enabled

Synchronous Transfer

Rate (Maximum)

Up to 600MB/s*

Buffer 128MB

Seek Time (typical reads,
includes controller
overhead, including
settling)Single Track
Average0.32ms*
7.45ms*Full Stroke14.2ms*

Operating Temperature 41° to 140° F (5° to 60° C)

Performance Sequential Read up to 226MB/s*

Sequential Write up to 226MB/s*

Enterprise Class Features High Reliability



^{*}Actual performance may vary.

^{*}Actual performance may vary.

Technical Specifications - Hard Drives

4TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class)

Capacity 4TB

Height 0.275 in; 0.7 cm

Width **Media Diameter** 2.5 in; 6.36 cm

Physical Size 2.75 in; 6.99 cm Serial ATA (6Gb/s), NCQ enabled

Synchronous Transfer Up to 600MB/s*

Rate (Maximum)

Buffer 128MB

Seek Time (typical reads, Single Track 0.7ms* includes controller **Average** 8.5ms* overhead, including **Full Stroke** 15.7ms*

settling)

Interface

Rotational Speed 7,200 rpm

32° to 140° F (0° to 60° C) **Operating Temperature**

*Actual performance may vary.

500GB SATA 7.2K SED SFF Capacity 500GB

HDD

0.275 in; 0.7 cm Height

Width **Media Diameter** 2.5 in; 6.36 cm **Physical Size** 2.75 in; 6.99 cm

Interface Serial ATA (6Gb/s) Up to 600MB/s*

Synchronous Transfer Rate (Maximum)

Buffer 32MB

Seek Time (typical reads, Single Track 1ms* includes controller 4.2ms* **Average** overhead, including **Full Stroke** 25ms (typical)*

settling)

Rotational Speed 7,200 rpm

32° to 140° F (0° to 60° C) **Operating Temperature**

*Actual performance may vary.



Technical Specifications - Hard Drives

SATA SSDs for	ΗP
Workstations	

HP 256GB SATA 6Gb/s

SSD

Capacity 256GB **Protocol** SATA **Form Factor** 2.5" Controller AHCI **NAND Type** 3D TLC

192TBW (TB Written) **Endurance**

Reliability (MTTF) 1.5M hours Physical Size (Height) 0.28 in; 0.7 cm Physical Size (Width) 2.5 in; 6.36 cm Interface SATA 6Gb/s **Synchronous Transfer** Up to 600MB/s*

Rate (Maximum)

Operating Temperature

32° to 158° F (0° to 70° C)

Performance

Seguential Read 530MB/s (max)* **Sequential Write** 500MB/s (max)* Random Read 55K IOPS (max)* Random Write 83K IOPS (max)*

HP 256GB SATA 6Gb/s SED Opal 2 SSD

256GB Capacity **Protocol** SATA **Form Factor** 2.5" Controller AHCI **NAND Type** 3D TLC

Endurance 192TBW (TB Written)

Reliability (MTTF) 1.5M hours Physical Size (Height) 0.28 in; 0.7 cm Physical Size (Width) 2.5 in; 6.36 cm Interface 6Gb/s SATA

Synchronous Transfer

Rate (Maximum)

Up to 550MB/s (Sequential Read)*

Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read 530MB/s* **Sequential Write** 500 MB/s* Random Read **55K IOPS*** Random Write 83K IOPS*

Self-Encrypting Drive

Support

OPAL 2

*Actual performance may vary.

HP 512GB SATA 6Gb/s

SSD

Capacity 512GB **Protocol** SATA 2.5" Form Factor Controller AHCI **NAND Type** 3D TLC

Endurance 388TBW (TB Written)

^{*}Actual performance may vary.

530 MB/s*

QuickSpecs

Technical Specifications - Hard Drives

Reliability (MTTF) 1.5M hours

Physical Size (Height) 0.28 in; 0.7 cm

Physical Size (Width) 2.5 in; 6.36 cm

Interface SATA 6Gb/s

Synchronous Transfer Rate (Maximum)

Up to 550MB/s (Sequential Read)*

Operating Temperature

32° to 158° F (0° to 70° C)

Sequential Read

Performance

Sequential Write 500 MB/s*
Random Read 95K IOPS*
Random Write 83K IOPS*

*Actual performance may vary.

HP 512GB SATA SED SSD

Capacity512GBProtocolSATAForm Factor2.5"ControllerAHCINAND Type3D TLC

Endurance 388TBW (TB Written)

Reliability (MTTF) 1.5M hours

Physical Size (Height) 0.28 in; 0.7 cm

Physical Size (Width) 2.5 in; 6.36 cm

Interface SATA 6Gb/s

Synchronous Transfer Up to 600MB/s*

Synchronous Transfer Rate (Maximum)

Operating Temperature

32° to 158° F (0° to 70° C)

Performance Sequential Read 530 MB/s*

Sequential Write 500 MB/s*
Random Read 95K IOPS*
Random Write 83K IOPS*

Up to 550MB/s (Sequential Read)*

Self-Encrypting Drive

Support

OPAL 1 and 2

*Actual performance may vary.

HP 1TB SATA 6Gb/s SSD

Capacity1TBProtocolSATAForm Factor2.5"ControllerAHCINAND Type3D TLC

Endurance 400TBW (TB Written)

Reliability (MTTF) 1.5M hours
Physical Size (Height) 0.28 in; 0.7 cm
Physical Size (Width) 2.5 in; 6.36 cm
Interface SATA 6Gb/s

Synchronous Transfer

Rate (Maximum)

Operating Temperature 32° to 158° F (0° to 70° C)



Technical Specifications - Hard Drives

Performance	Sequential Read	530 MB/s*
	Sequential Write	500 MB/s*

95K IOPS* Random Read Random Write 83K IOPS*

*Actual performance may vary.

HP 2TB SATA 6Gb/s SSD Capacity 2TB

> **Protocol** SATA **Form Factor** 2.5" Controller AHCI 3D TLC **NAND Type**

Endurance 400TBW (TB Written)

Reliability (MTTF) 1.5M hours Physical Size (Height) 0.28 in; 0.7 cm Physical Size (Width) 2.5 in; 6.36 cm Interface SATA 6Gb/s

Synchronous Transfer

Rate (Maximum)

Up to 550MB/s (Sequential Read)*

Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read 530 MB/s* **Sequential Write** 500 MB/s *

> Random Read 95K IOPS* Random Write 83K IOPS*

*Actual performance may vary.

HP Enterprise Class 240GB SATA SSD

Capacity 240GB **Protocol SATA** Form Factor 2.5" Controller AHCI **NAND Type** 3D TLC

Endurance 2,200TBW (TB Written)

Reliability (MTTF) 2.0M hours Physical Size (Height) 0.28 in; 0.7 cm Physical Size (Width) 2.5 in; 6.36 cm Interface 6Gb/s SATA **Synchronous Transfer** Up to 600MB/s*

Rate (Maximum)

Operating Temperature

32° to 158° F (0° to 70° C)

Performance **Sequential Read**

540 MB/s* **Sequential Write** 310 MB/s* Random Read 93K IOPS*

Random Write 48K IOPS*

Enterprise Class Features High Endurance NAND

> **Power Loss Protection End-to-End Data Protection**

*Actual performance may vary.



Technical Specifications - Hard Drives

HP Enterprise Class
480GB SATA SSD

Capacity 480GB **Protocol** SATA **Form Factor** 2.5" Controller AHCI **NAND Type** 3D TLC

4,400TBW (TB Written) **Endurance**

Reliability (MTTF) 2.0M hours Physical Size (Height) 0.28 in; 0.7 cm Physical Size (Width) 2.5 in; 6.36 cm Interface 6Gb/s SATA **Synchronous Transfer** Up to 600MB/s*

Rate (Maximum)

Operating Temperature

32° to 158° F (0° to 70° C)

Performance

Seguential Read 540 MB/s* **Sequential Write** 460 MB/s* Random Read 93K IOPS* Random Write 74K IOPS*

Enterprise Class Features

High Endurance NAND Power Loss Protection End-to-End Data Protection

Performance PCIe SSDs for HP Workstations

HP Z Turbo Drive 256GB M.2 2280 TLC SSD

Capacity 256GB **Protocol PCIe** Form Factor M.2 Controller NVMe **NAND Type** 3D TLC **SED Support** Opal 2 **Endurance** 200TB Reliability (MTBF) 1.5M hours

Interface PCI Express 3.0 x4 electrical x4 physical

Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read 3500 MB/s *

> **Sequential Write** 2200 MB/s * 240K IOPS * Random Read **Random Write** 480K IOPS *

HP ZTurbo Drive 512GB M.2 2280 TLC SSD

Capacity 512GB Protocol **PCIe Form Factor** M.2 Controller NVMe 3D TLC **NAND Type SED Support** Opal 2 **Endurance** 300TB Reliability (MTBF) 1.5M hours

^{*}Actual performance may vary.

^{*}Actual performance may vary.

Technical Specifications - Hard Drives

Interface	PCI Express 3.0 x4 electrical x4 physical
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Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read 3500 MB/s*

1TB

Sequential Write 2900 MB/s*
Random Read 460 K IOPS*
Random Write 500K IOPS*

HP ZTurbo Drive 1TB M.2 Capacity 2280 TLC SSD Protocol

Protocol PCIe
Form Factor M.2
Controller NVMe
NAND Type 3 D TLC
SED Support Opal 2
Endurance 400TB
Reliability (MTBF) 1.5M hours

Interface PCI Express 3.0 x4 electrical x4 physical

Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read 3500 MB/s*

Sequential Write 3000 MB/s*
Random Read 580K IOPS*
Random Write 500K IOPS*

HP ZTurbo Drive 2TB M.2 2280 TLC SSD

Capacity 2TB **PCIe Protocol** Form Factor M.2 Controller NVMe 3D TLC **NAND Type SED Support** Opal 2 **Endurance** 500TB Reliability (MTTF) 1.5M hours

Interface PCI Express 3.0 x4 electrical x4 physical

Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read 3300 MB/s*

Sequential Write 2400 MB/s*
Random Read 500K IOPS*
Random Write 440K IOPS*

*Actual performance may vary.

Performance PCIe SSDs for HP Workstations

HP Z Turbo Drive Quad Pro 2x256GB PCle TLC SSD Capacity512GBProtocolPCIe

Form Factor PCIe Card, Full Height PCIe Slot

Controller NVMe

^{*}Actual performance may vary.

^{*}Actual performance may vary.

Technical Specifications - Hard Drives

NAND Type 3D TLC
SED Support Opal 2
Endurance 200TB
Reliability (MTBF) 1.5M hours

Interface PCIe Gen3 x4 architecture
Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read 3500 MB/s*

Sequential Write 2200 MB/s*
Random Read 240K IOPS*
Random Write 480K IOPS*

HP Z Turbo Drive Quad Pro 2x512GB PCle TLC SSD Capacity1TBProtocolPCIe

Form Factor PCIe Card, Full Height PCIe Slot

Controller NVMe
NAND Type 3D TLC
SED Support Opal 2
Endurance 300TB
Reliability (MTBF) 1.5M hours

Interface PCIe Gen3 x4 architecture
Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read 3500 MB/s*

Sequential Write 2900 MB/s*
Random Read 460 K IOPS*
Random Write 500K IOPS*

HP Z Turbo Drive Quad Pro Capacity 2x1TB PCIe TLC SSD Protocol

Capacity 2TB
Protocol PCle

Form Factor PCIe Card, Full Height PCIe Slot

ControllerNVMeNAND Type3D TLCSED SupportOpal 2Endurance400TB

Interface PCI Express 3.0 x4 electrical x4 physical

Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read 3500 MB/s*

Sequential Write 3000 MB/s*
Random Read 580K IOPS*
Random Write 500K IOPS*

Capacity 256GB



^{*}Actual performance may vary.

^{*}Actual performance may vary.

^{*}Actual performance may vary.

Technical Specifications - Hard Drives

HP Z Turbo Drive Dual Pro Protocol **256GB SSD**

PCIe

Form Factor M.2 in Half-height, half-length card

Controller NVMe **NAND Type** 3D TLC

200TBW (TB Written) **Endurance**

Reliability (MTBF) 1.5M hours

Interface PCI Express 3.0 x4 electrical x4 physical

Operating Temperature 32° to 158° F (0° to 70° C)

Performance Seguential Read 3500 MB/s*

> **Sequential Write** 2200 MB/s* Random Read 240K IOPS* Random Write 480K IOPS*

HP Z Turbo Drive Dual Pro Capacity **512GB SSD**

512GB Protocol PCle

Form Factor M.2 in Half-height, half-length card

Controller NVMe NAND Type 3D TLC

Endurance 300TBW (TB Written)

Reliability (MTBF) 1.5M hours

Interface PCI Express 3.0 x4 electrical x4 physical

32° to 158° F (0° to 70° C) **Operating Temperature**

Performance **Sequential Read** 3500 MB/s*

> Sequential Write 2900 MB/s* **Random Read** 460 K IOPS* **Random Write** 500K IOPS*

HP Z Turbo Drive Dual Pro Capacity 1TB SSD

Protocol

PCIe

Form Factor M.2 in Half-height, half-length card

1TB

Controller NVMe **NAND Type** 3D TLC

400TBW (TB Written) **Endurance**

Reliability (MTBF) 1.5M hours

Interface PCI Express 3.0 x4 electrical x4 physical

Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read 3500 MB/s*

> **Sequential Write** 3000 MB/s* Random Read 580K IOPS* Random Write 500K IOPS*



^{*}Actual performance may vary.

^{*}Actual performance may vary.

^{*}Actual performance may vary.

Technical Specifications - Hard Drives

HP Z Turbo Drive Dual Pro Capacity 2TB SSD

2TB **PCle** Protocol

Form Factor M.2 in Half-height, half-length card

Controller NVMe **NAND Type** 3D TLC

500TBW (TB Written) **Endurance**

Reliability (MTBF) 1.5M hours

Interface PCI Express 3.0 x4 electrical x4 physical

Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read 3500 MB/s*

> Sequential Write 3000 MB/s * Random Read 600K IOPS* Random Write **500K IOPS***

Mainstream PCIe SSDs for HP 256GB M.2 2280 TLC **HP Workstations** SSD

Capacity 256GB **Protocol PCIe** Form Factor M.2 Controller NVMe 3D TLC **NAND Type** 200TB **Endurance** Reliability (MTBF) 1.5M hours

Interface PCI Express 3.0 x4 electrical x4 physical

Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read 3100 MB/s *

> Sequential Write 1400 MB/s * Random Read 200 K IOPS * **Random Write** 320 K IOPS *

HP 512GB M.2 2280 TLC **SSD**

Capacity 512GB **PCIe** Protocol M.2 Form Factor Controller NVMe **NAND Type** 3D TLC **Endurance** 300TB Reliability (MTBF) 1.5M hours

Interface PCI Express 3.0 x4 electrical x4 physical

Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read 3300 MB/s*

> **Sequential Write** 2500 MB/s* Random Read 225 K IOPS* **Random Write** 430 K IOPS*



^{*}Actual performance may vary.

^{*}Actual performance may vary.

^{*}Actual performance may vary.

Technical Specifications - Hard Drives

HP 1TB M.2 2280 TLC SSD Capacity 1TB

Protocol PCIe
Form Factor M.2
Controller NVMe
NAND Type 3D TLC
Endurance 400TB
Reliability (MTBF) 1.5M hours

Interface PCI Express 3.0 x4 electrical x4 physical

Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read 3300 MB/s*

Sequential Write 2500 MB/s*
Random Read 400 K IOPS*
Random Write 440 K IOPS*

HP 2TB M.2 2280 TLC SSD Capacity 2TB

Protocol PCIe
Form Factor M.2
Controller NVMe
NAND Type 3 D TLC
Endurance 500TB
Reliability (MTBF) 1.5M hours

Interface PCI Express 3.0 x4 electrical x4 physical

Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read 3300 MB/s*

Sequential Write 2700 MB/s*
Random Read 430 K IOPS*
Random Write 500 K IOPS*

Intel® 905p Series AIC PCIe Intel® 905p Series AIC SSD 280GB PCIe SSD

Capacity 280GB Protocol PCIe

Form Factor PCIe Card, Half Height

Controller NVMe NVM Type 3DXPoint

Endurance 5.11 PBW (PB Written)

Reliability (MTBF) 1.6M hours

Operating Temperature 32° to 185° F (0° to 85° C)

Performance Sequential Read 2730 MB/s*

Sequential Write 2280 MB/s*
Random Read 587K IOPS*
Random Write 559K IOPS*

*Actual performance may vary.

Capacity 480GB



^{*}Actual performance may vary.

^{*}Actual performance may vary.

Technical Specifications - Hard Drives

Protocol PCIe

Form Factor PCIe Card, Half Height

Controller NVMe NVM Type 3DXPoint

Endurance 8.76 PBW (PB Written)

Intel® 905p Series AIC 480GB PCIe SSD

Reliability (MTBF) 1.6M hours

Operating Temperature 32° to 185° F (0° to 85° C)

Performance Sequential Read 2710 MB/s*

Sequential Write 2280 MB/s*
Random Read 582K IOPS*
Random Write 561K IOPS*

Intel® Optane™ DC Persistent Memory Intel® Optane™ DC Capacity
Persistent Memory 128GB
Module Protocol

Capacity128GBProtocolDDR-TForm FactorDDR4ControllerNVMeNVM Type3DXPoint

Endurance 292 PBW (256B Sequential Write)

91 PBW (64B Sequential Write)

Reliability (MTBF) 2M hours

Operating Temperature 32° to 185° F (0° to 85° C)

Performance Sequential Read 6800 MB/s*

Sequential Write 1850 MB/s*

^{*}Actual performance may vary.

^{*}Actual performance may vary.

Technical Specifications - Hard Drive Controllers

HARD DRIVE CONTROLLERS

MicroSemi 2100-4i4e 8-**PCI Bus** 8 lanes, PCI Express 3.0

port SAS 12Gb/s RAID Card RAID Levels Offers Integrated RAID (0, 1, and 10) Half Duplex x8, PCIe, 8000 MB/s

PCI Data Burst Transfer

Rate

SAS Bandwidth Half Duplex 1200 MB/s per lane

PCI Card Type 3.3V Add-in Card 12 V ± 10% **PCI Voltage**

PCI Power 9.8W typical, Airflow min 200 LFM

Bracket Full height and low profile **Certification Level** PCI Express 3.0 compliant

SAS Processor MicroSemi Series 8 SAS Controller **Internal Connectors** One x4 internal mini-SASHD (SFF-8643) **External Connectors** One x4 external mini-SASHD (SFF-8644)

Maximum Number of SCSI 256 Non-RAID SAS/SATA devices

Devices

LED Indicators

Connector for Drive Activity Light

NOTE: RAID 5 is not supported on MicroSemi 2100-4i4e 8-port SAS 12Gb/s

RAID Card



Technical Specifications - Graphics

GRAPHICS

NVIDIA® Quadro® P400

2GB Graphics

Form Factor Dimensions: 2.713" H x 5.7" L

Single Slot, Low Profile

Cooling: Active Weight: 129 grams

Graphics Controller NVIDIA® Quadro® P400 Graphics Card

GP107 GPU

256 NVIDIA® CUDA® cores Max Power: 30 Watts PCI Express 3.0 x16

Bus Type PCI Express 3.0 x16

Memory Size: 2 GB GDDR5, 2000 MHz

Memory Interface: 64-bit Memory Bandwidth: 32 GB/s

Connectors 3mDP Outputs

Maximum Resolution DisplayPort™ 1.4:

- up to 3x 5120 x 2880 x 24 bpp @ 60Hz- supports Multi-Stream Transport (MST)

Image Quality Features 10-bit internal display processing pipeline

10-bit scan-out support

Display Output 3 mDP Connectors

Shading Architecture Full Microsoft DirectX® 12 Shader Model 5.1

Supported Graphics APIs OpenGL® 4.5

DirectX® 12 Vulkan™ 1.0

API support includes:

CUDA C, CUDA C++, DirectCompute, OpenCL™

Available Graphics Drivers Windows 11

Windows 10

Windows 8.1 (via nvidia.com unless deprecated

Windows 7 (via nvidia.com)

Linux®

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

Notes

NVIDIA® Quadro® P620 2GB Graphics Form Factor Dimensions: 2.713" H x 5.7" L

Single Slot, Low Profile Cooling: Active Weight: 129 grams

Graphics Controller NVIDIA® Quadro® P620 Graphics Card

GP107 GPU 512 CUDA cores Max Power: 40 Watts

Bus Type PCI Express 3.0 x16



Technical Specifications - Graphics

Memory Size: 2 GB GDDR5, 2000 MHz

Memory Interface: 128-bit Memory Bandwidth: 64 GB/s

Connectors 4mDP Outputs * **Maximum Resolution** DisplayPort™ 1.4:

- up to 4x 5120 x 2880 x 24 bpp @ 60Hz- supports Multi-Stream Transport (MST)

Image Quality Features 10-bit internal display processing pipeline

10-bit scan-out support

Display Output 4 mDP Connectors

Shading Architecture Full Microsoft DirectX 12 Shader Model 5.1

Supported Graphics APIs OpenGL 4.5

DirectX 12 Vulkan 1.0

API support includes:

CUDA C, CUDA C++, DirectCompute, OpenCL

Available Graphics Drivers Windows 11

Windows 10

Windows 7 (via nvidia.com)

Linux®

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html *P620 only have mini-DisplayPort™ (mDP) video ports.

Notes *P620 only have mini-DisplayPort™ (mDP) video ports.

Factory Configured (Z4 G4/ Z6 G4/ Z8 G4 Workstations): No adapters

included

After market option kit:Two mDP-to-DP Adapters included

Additional mDP-to-DP Adapters are available as Factory Configuration or

Option Kit accessories:

2MY05AA - HP miniDP-to-DP Adapter Cables

- 2KW87A6 - HP (Bulk 12) miniDP-to-DP Adapter Cables

NVIDIA® T400 2GB Graphics Form Factor Dimensions: 2.713" H x 6.137" L

Single Slot, Low Profile

Weight: 124g

Graphics Controller NVIDIA® T400 Graphics Card

GPU: 384 CUDA cores Power: 30 Watts Cooling: Active

Bus Type PCI Express 3.0 x16

Memory Size: 2 GB GDDR6

Memory Interface: 64

Memory Interface: 64-bit Memory Bandwidth: 80 GB/s

Connectors 3x mDP

Technical Specifications - Graphics

Maximum Resolution 3x 5120 x 2880 x 24 bpp @ 60Hz

Supported Graphics APIs OpenGL 4.5

DirectX 12 Vulkan 1.0

API support includes: CUDA, OpenCL 1.x

Available Graphics Drivers Windows 11

Windows 10 Linux

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

NVIDIA® T600 4GB Graphics

Form Factor Dimensions: 2.713" H x 6.137" L

Single Slot, Low Profile

Weight: 130g

Graphics Controller NVIDIA® T600 Graphics Card

GPU: 640 CUDA cores Power: 40 Watts Cooling: Active

Bus Type PCI Express 3.0 x16

Memory Size: 4 GB GDDR6

Memory Interface: 128-bit Memory Bandwidth: 160 GB/s

Connectors 4x mDP

Maximum Resolution 4x 5120 x 2880 x 24 bpp @ 60Hz

Supported Graphics APIs OpenGL 4.5

DirectX 12 Vulkan 1.0

API support includes:

CUDA C, CUDA C++, DirectCompute, OpenCL

Available Graphics Drivers Windows 11

Windows 10 Linux

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

NVIDIA® Quadro® P1000

4GB Graphics

Form Factor Dimensions:2.713" H x 5.7" L

Single Slot, Low Profile

Cooling: Active Weight: 129 grams

Graphics Controller NVIDIA® Quadro® P1000 Graphics Card

GP107-860 GPU

640 NVIDIA® CUDA® cores Max Power: 47 Watts

Bus Type PCI Express 3.0 x16

Technical Specifications - Graphics

Memory Size: 4 GB GDDR5, 2500 MHz

Memory Interface: 128-bit memory interface Memory Bandwidth: 80 GB/s memory bandwidth

Connectors4mDP OutputsMaximum ResolutionDisplayPort™ 1.4:

- up to 4x 5120 x 2880 x 24 bpp @ 60Hz - supports Multi-Stream Transport (MST)

Image Quality Features 10-bit internal display processing pipeline

10-bit scan-out support

Display Output 4 mDP Connectors

Shading Architecture Full Microsoft DirectX® 12 Shader Model 5.1

Supported Graphics APIs OpenGL® 4.5

DirectX® 12 Vulkan™ 1.0 API support includes:

CUDA C, CUDA C++, DirectCompute, OpenCL™

Available Graphics Drivers Windows 11

Windows 10

Windows 7 (via nvidia.com)

Linux®

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

Notes

NVIDIA® Quadro® P2000

5GB Graphics

Form Factor Dimensions: 4.4"Hx7.9"L

Single Slot Cooling: Active Weight: 260 grams

Graphics Controller NVIDIA® Quadro® P2000 Graphics Card

Power: 75 Watts

Bus TypePCI Express 3.0 x16MemorySize: 5GB GDDR5

Memory Bandwidth: 140 GB/s

Memory Width: 160-bit

Connectors 4x DisplayPort™ 1.4

Factory Configured Option: No adapter included with card After Market Option: No video cable adapter included

Additional DVI to VGA, DisplayPort™ to VGA, DisplayPort™ to DVI, and DisplayPort™ to Dual-Link DVI adapters available as accessories.

Maximum Resolution DisplayPort™:

- up to 5120 x 2880 x 24 bpp @ 60Hz

- supports High Bit Rate 2 (HBR2) and Multi-Stream Transport (MST) DP 1.3

& 1.4 ready.

DL-DVI(I) output:

- up to 2560 x 1600 x 32 bpp @ 60 Hz



Technical Specifications - Graphics

Single Link-DVI(I) output:

- up to 1920 x 1200 x 32 bpp @ 60Hz

HDMI 2.0 (requires DP to HDMI adapter):

5120 x 2880 x 24 bpp @ 60Hz

Image Quality Features 12-bit internal display pipeline (hardware support for 12-bit scanout on

supported panels, applications and connection)

Stereoscopic 3D display support including NVIDIA® 3D Vision™ technology,

NVIDIA® Mosaic and nView.

Display Output Maximum number of displays

- 4 direct attached monitors

Maximum number of monitors across all available NVIDIA® Quadro® P2000

outputs is 4.

Shading Architecture

Supported Graphics APIs

Shader Model 5.1 OpenGL® 4.5

DirectX[®] 12

API support includes:

CUDA C, CUDA C++, DirectCompute 5.0, OpenCL™, Java, Python, and Fortran

software

Available Graphics Drivers Windows 11

Windows 10

Windows 7 Professional (via nvidia.com)

Linux® - Full OpenGL® implementation, complete with NVIDIA® Quadro®

and ARB extensions

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

Notes

NVIDIA® Quadro® P2200

5GB Graphics

Form Factor Dimensions: 4.4"H x 7.9"L

Single Slot, Full Height Weight: 260 grams

Graphics Controller NVIDIA® Quadro® P2200 Graphics Card

GPU: 1280 CUDA cores Power: 75 Watts Cooling: Active

Bus Type PCI Express 3.0 x16
Memory Size: 5GB GDDR5X

Memory Bandwidth: 200 GB/s Memory Width: 160-bit

Connectors 4x DisplayPort[™] 1.4

Factory Configured Option: No adapter included with card After Market Option: No video cable adapter included



Technical Specifications - Graphics

Additional DVI to VGA, DisplayPort™ to VGA, DisplayPort™ to DVI, and DisplayPort™ to Dual-Link DVI adapters available as accessories.

Maximum Resolution

DisplayPort™:

- up to 5120 x 2880 x 24 bpp @ 60Hz

- supports High Bit Rate 2 (HBR2) and Multi-Stream Transport (MST) DP 1.3

& 1.4 ready.

DL-DVI(I) output:

- up to 2560 x 1600 x 32 bpp @ 60 Hz

Single Link-DVI(I) output:

- up to 1920 x 1200 x 32 bpp @ 60Hz

HDMI 2.0 (requires DP to HDMI adapter):

5120 x 2880 x 24 bpp @ 60Hz

Image Quality Features

12-bit internal display pipeline (hardware support for 12-bit scanout on

supported panels, applications and connection)

Stereoscopic 3D display support including NVIDIA® 3D Vision™ technology,

NVIDIA® Mosaic and nView.

Display Output

Maximum number of displays
- 4 direct attached monitors

Maximum number of monitors across all available NVIDIA® Quadro® P2200

outputs is 4.

Shading Architecture

Supported Graphics APIs

Shader Model 5.1 OpenGL® 4.5

DirectX® 12

API support includes:

CUDA C, CUDA C++, DirectCompute 5.0, OpenCL™, Java, Python, and Fortran

software

Available Graphics Drivers Windows 11

Windows 11

Windows 7 Professional (via nvidia.com)

Linux® - Full OpenGL® implementation, complete with NVIDIA® Quadro® and

ARB extensions

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

Notes

 Quadro P2200 offered as Factory Configured Option does not include a video cable adapter. Video cable adapters must be

ordered separately.

2. Quadro P2200 offered as an After Market Option does not include video cables. Video cable adapters must be ordered separately.

AMD Radeon™ Pro WX 3200 4GB Graphics

Form Factor
Graphics Controller

Low-Profile Single Slot (2.75 "H x 6.6" L) Radeon™ Pro WX 3200 Graphics Card

GPU: 640 Stream Processors organized into 8 Compute Units

Power: 56 Watts Cooling: Active

Technical Specifications - Graphics

Memory 4GB GDDR5 memory

Memory Bandwidth: 6 Gbps / 96 GB/s

Memory Width: 128 bit

Connectors 2x Mini DisplayPort™ 1.4 plus 1x DisplayPort™ 1.4 – HDR ready connectors

with HBR3 and MST support.

Factory Configured: No adapters included

After market option kit: One mDP-to-DP cable adapters included

Additional Mini DisplayPort™-to-DisplayPort™, DisplayPort™-to-VGA or DisplayPort™-to-DVI adapters are available as Factory Configuration or

Option Kit accessories.

Maximum Resolution 5K support @ 60Hz

• 1x single-cable 5K monitor, or 2x dual-cable 5K monitors

3x 4K support @ 60Hz

Image Quality Features Advanced support for 8-bit and 10-bit per RGB color component. High

bandwidth scaler for high quality up and downscaling

Display Output 3 full physical DP1.3 HBR3 / DP1.4 HDR outputs

FreeSync support

GPU Architecture Polaris

Supported Graphics APIs DirectX°12

OpenGL® 4.5 OpenCL™ 2.0 Vulkan™ 1.0

Available Graphics Drivers Windows 11

Windows 10

(Windows® 7 64-bit available from AMD) Linux® 64-bit (selected Enterprise distributions)

 $\label{eq:heaviside} \mbox{HP qualified drivers may be preloaded or available from the HP support}$

Web site:

http://welcome.hp.com/country/us/en/support.html

Notes

- HDR content requires that the system be configured with a fully HDR-ready content chain, including: graphics card, monitor/TV, graphics driver and application. Video content must be graded in HDR and viewed with an HDR-ready player. Windowed mode content requires operating system support.
- 2. AMD PowerTune and AMD ZeroCore Power are technologies offered by certain FirePro™ and Radeon™ Pro products, which are designed to intelligently manage GPU power consumption in response to certain GPU load conditions.
- 3. As of September 2016, certified for DisplayPort™ 1.4 HBR3 and ready for DisplayPort™ 1.4 HDR based on independent verification by DisplayPort™ testing authority. HDR content requires that the system be configured with a fully HDR-ready content chain, including: graphics card, monitor/TV, graphics driver and application. Video content must be graded in HDR and viewed with an HDR-ready player. Windowed mode content requires operating system support.



Technical Specifications - Graphics

NVIDIA® T1000 4GB Graphics Form Factor Dimensions: 2.713" H x 6.137" L

Single Slot Weight: xx

Graphics Controller NVIDIA® T1000 Graphics Card

Power: 50W Cooling: Active

Bus TypePCI Express 3.0 x16MemorySize: 4GB GDDR6

Memory Bandwidth: Up to 160 GB/s

Memory Width: 128-bit

Connectors4x mini DisplayPort™ 1.4aMaximum Resolution7680 x 4320 @ 120Hz

Display Output Maximum number of displays: 4 displays

Architecture NVIDIA® Turing™

Supported Graphics APIs xx

Available Graphics Drivers Windows 11

Windows 10 Windows 8.1

Windows 7 Professional

Linux® - Full OpenGL® implementation, complete with NVIDIA® Quadro® and

ARB extensions

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

NVIDIA® RTX A2000 6GB

Graphics

Form Factor Dimensions: 2.713" H x 6.6" L

Dual slot, half-height

Weight: 295 grams (without extender)

Graphics Controller NVIDIA® RTX A2000 Graphics Card

Power: 70W Cooling: Active PCI Express 4.0 x1

Bus TypePCI Express 4.0 x16MemorySize: 6GB GDDR6

Memory Bandwidth: Up to 288 GB/s

Memory Width: 192-bit

Connectors 4x mini-DisplayPort™ 1.4a

Maximum Resolution Up to 4x 5120 x 2880 x 24bpp @ 60Hz

ArchitectureNVIDIA® Ampere™Supported Graphics APIsCUDA, OpenCL™ 1.x

Available Graphics Drivers Windows 11

Windows 10

Linux® 64-bit (selected Enterprise distributions)

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html



Technical Specifications - Graphics

Notes

- RTX A2000 offered as Factory Configured Option does not include a video cable adapter. Video cable adapters must be ordered separately as AMO:
 - a. 2MY05AA HP Single miniDP-to-DP Adapter Cable
 - b. 2KW87A6 HP (Bulk 12) miniDP-to-DP Adapter Cables
- 2. Two mDP-to-DP adapters are included with the RTX A2000 when it is ordered as an AMO kit.

NVIDIA® Quadro® RTX™ Form Factor

4000 8GB Graphics

Full-Height Single Slot (4.4" Height x 9.5" Length)

Weight: 550 grams / 1.21 lbs

Graphics Controller NVIDIA® Quadro® RTX™ 4000 Graphics

TU104 GPU

GPU: 2304 NVIDIA® CUDA® Parallel Processing Cores

Power: 160 Watts Cooling: Active

Memory 8GB GDDR6 memory

Memory Bandwidth: Up to 416 GB/s

Memory Width: 384 bit

Connectors 3x DP 1.4a and VirtualLink

Quadro Sync connector (compatible with Quadro II Sync)

One 8-pin auxiliary power connector

Factory configured option: No video cable adapter included with

card.

After market option Kit: No video cable adaptor included with card.

DVI to VGA, DisplayPort[™] to VGA, DisplayPort[™] to DVI, and DisplayPort[™] to Dual-Link DVI adapters available as accessories.

Maximum Resolution 7680x4320 @ 60Hz

Image Quality Features Advanced support for 8-bit, 10-bit, and 12-bit per RGB

color component.

HDCP 2.2 support over DisplayPort™, DVI, and HDMI

connectors

NVIDIA® 3D Vision™ and other 3D stereo technologies

NVIDIA® Mosaic and nView

Display Outputs¹ 3x DP 1.4a and VirtualLink (7680x4320 @ 60Hz)

Supported Graphics

APIs

DirectX°12, OpenGL° 4.5, OpenCL™ 1.0, Vulkan™ 1.0

Developer API support includes: CUDA C, CUDA C++, DirectCompute

5.0, OpenCL™, Java, Python, and Fortran

Technical Specifications - Graphics

Available Graphics

Drivers

Windows 11 Windows 10

Windows 7 (via nvidia.com)

Linux® 64-bit

HP qualified drivers may be preloaded or available from the HP

support Web site:

http://welcome.hp.com/country/us/en/support.html

Notes 1- Supports up to a total of 4 displays

NVIDIA® RTX A4000 16GB Graphics Form Factor

Full-Height Single Slot (4.4" Height x 9.5" Length)

Graphics Controller

NVIDIA® RTX A4000 Graphics

GPU: 6144 NVIDIA® CUDA® Parallel Processing Cores

Power: 140 Watts Cooling: Active

Memory

16GB GDDR6 memory

Memory Bandwidth: Up to 448 GB/s

Memory Width: 256 bit

Connectors

4x DP

One 6-pin auxiliary power connector

Factory configured option: No video cable adapter included with

card.

After market option Kit: No video cable adaptor included with card.

DVI to VGA, DisplayPort™ to VGA, DisplayPort™ to DVI, and DisplayPort™ to Dual-Link DVI adapters available as accessories.

Maximum Resolution

7680x4320 @ 60Hz

Display Outputs¹

4x DP

Supported Graphics

APIs

DirectX°12, OpenGL° 4.5, OpenCL™ 1.0, Vulkan™ 1.0

Developer API support includes: CUDA C, CUDA C++, DirectCompute

5.0, OpenCL™, Java, Python, and Fortran

Available Graphics

Drivers

Windows 11

Windows 10 Linux® 64-bit

HP qualified drivers may be preloaded or available from the HP

support Web site:

http://welcome.hp.com/country/us/en/support.html

Technical Specifications - Graphics

NVIDIA® RTX A4500 20GB Graphics Form Factor Full-Height Dual Slot (4.4" Height x 10.5" Length)

Graphics Controller NVIDIA® RTX A4500 Graphics

GPU: 7168 NVIDIA® CUDA® Parallel Processing Cores

Power: 200 Watts Cooling: Active

Memory 20GB GDDR6 memory

Memory Bandwidth: Up to 640 GB/s

Memory Width: 320 bit

Connectors 4x DP

One 8-pin auxiliary power connector

Factory configured option: No video cable adapter included with

card.

After market option Kit: No video cable adaptor included with card.

DVI to VGA, DisplayPort™ to VGA, DisplayPort™ to DVI, and DisplayPort™ to Dual-Link DVI adapters available as accessories.

Maximum Resolution 7680x4320 @ 60Hz

Display Outputs¹ 4x DP

Supported Graphics

APIs

DirectX°12, OpenGL° 4.5, OpenCL™ 1.0, Vulkan™ 1.0

Developer API support includes: CUDA C, CUDA C++, DirectCompute

5.0, OpenCL™, Java, Python, and Fortran

Available Graphics

Drivers

Windows 11 Windows 10

Linux® 64-bit

HP qualified drivers may be preloaded or available from the HP

support Web site:

http://welcome.hp.com/country/us/en/support.html

NVIDIA® Quadro® RTX™ Form Factor

5000 16GB Graphics

Full-Height Dual Slot (4.4" Height x 10.5" Length)

Weight: 1050 grams / 2.31 lbs

Graphics Controller

NVIDIA® Quadro® RTX™ 5000 Graphics

TU104 GPU

GPU: 3072 NVIDIA® CUDA® Parallel Processing Cores

Power: 265 Watts Cooling: Active



Technical Specifications - Graphics

Memory 16GB GDDR6 memory

Memory Bandwidth: Up to 448 GB/s

Memory Width: 384 bit

Connectors 4x DP 1.4a and VirtualLink

Quadro Sync connector (compatible with Quadro II Sync)

One 8-pin + 6-pin auxiliary power connector

Factory configured option: No video cable adapter included with

card.

After market option Kit: No video cable adaptor included with card.

DVI to VGA, DisplayPort™ to VGA, DisplayPort™ to DVI, and DisplayPort™ to Dual-Link DVI adapters available as accessories.

Maximum Resolution 7680x4320 @ 60Hz

Image Quality Features Advanced support for 8-bit, 10-bit, and 12-bit per RGB

color component.

HDCP 2.2 support over DisplayPort™, DVI, and HDMI

connectors

NVIDIA® 3D Vision™ and other 3D stereo technologies

NVIDIA® Mosaic and nView

Display Outputs¹ 4x DP 1.4a and VirtualLink (7680x4320 @ 60Hz)

Supported Graphics DirectX°12, OpenGL° 4.5, OpenCL™ 1.0, Vulkan™ 1.0

APIs

Developer API support includes: CUDA C, CUDA C++, DirectCompute

5.0, OpenCL™, Java, Python, and Fortran

Available Graphics

Drivers

Windows 11 Windows 10

Windows 7 (via nvidia.com)

Linux® 64-bit

HP qualified drivers may be preloaded or available from the HP

support Web site:

http://welcome.hp.com/country/us/en/support.html

Notes 1- Supports up to a total of 4 displays

NVIDIA® RTX A5000 24GB Graphics Form Factor Full-Height Dual Slot (4.4" Height x 10.5" Length)

Weight: 1049 grams + 80 grams extender

Graphics Controller NVIDIA® RTX A5000

GPU: 8192 CUDA Cores

Power: 230W Cooling: Active

Technical Specifications - Graphics

Memory 24GB GDDR6

Memory Bandwidth: Up to 768GB/s ECC Memory (disabled by default)

Connectors DP (x4) with HDR support

One 8-pin auxiliary power connector

After market option Kit: no power adapter included with card.

DisplayPort[™] to VGA, DisplayPort[™] to DVI (single-link and dual-link), and DisplayPort[™] to HDMI adapters available as accessories.

Maximum Resolution DisplayPort™ 1.4a:

7680x4320 @ 120Hz

Display Outputs 4x DP1.4a HDR2 outputs (up to 7680x4320 @ 120Hz)

GPU Architecture NVIDIA® Ampere™

Supported Graphics

APIs

DirectX®12, OpenGL® 4.5

Developer API support includes: CUDA C, CUDA C++, DirectCompute

5.0, OpenCL™, Java, Python, and Fortran

Available Graphics

Drivers

Windows 11 Windows 10

Windows 7

HP qualified drivers may be preloaded or available from the HP

support Web site:

http://welcome.hp.com/country/us/en/support.html

Factory Configured (Z4/Z6/Z8 G4 Workstation): No adapters

included

After market option kit: No adapters included

NVIDIA® RTX™ A6000 48GB Graphics Form Factor

Full-Height Dual Slot (4.4" Height x 10.5" Length) Weight: 1230 grams / 2.71 lbs (with extender)

Graphics Controller NVIDIA® RTX™ A6000 Graphics

GPU: 10752 NVIDIA® CUDA® Parallel Processing Cores

Power: 300 Watts Cooling: Active

Memory 48GB GDDR6 memory

ECC optional

Memory Bandwidth: Up to 768 GB/s

Memory Width: 384 bit

Connectors 4x DP 1.4a

Quadro Sync II connector

Ampere NVLink®



Technical Specifications - Graphics

Stereo Sync

Requires 8-pin CPU auxiliary power

Maximum Resolution 5120x2880 @ 60Hz (up to 4 displays)

Display Outputs 4x DP 1.4 (7680x4320 @ 60Hz)

Supported Graphics APIs DirectX°12, OpenGL° 4.6, OpenCL™ 1.0, Vulkan™ 1.0

Developer API support includes: CUDA C, CUDA C++, DirectCompute 5.0,

OpenCL™, Java, Python, and Fortran™

Available Graphics Drivers Windows 11

Windows 10 Linux® 64-bit

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

NVIDIA® Quadro® GV100 32GB Graphics Form Factor Dual Slot (4.4" Height x 10.5" Length)

Weight: 980 grams + 72 gram extender

Graphics Controller NVIDIA® QUADRO® GV100

GPU: 5120 NVIDIA® CUDA® Parallel Processing Cores

Power: 250 Watts Cooling: Active

Memory 32GB HBM2 memory

Memory Bandwidth: Up to 870 GB/s

Memory Width: 5120-bit

ECC Memory (disabled by default)

Connectors DP (x4) with HDR support

3-pin mini-DIN connector via optional bracket

4-pin header for stereo signal

Quadro Sync connector (compatible with Quadro II Sync)

One 8-pin auxiliary power connector

(2x) NVLink for GV100 connectors (via optional kit)

After market option Kit: no power adapter included with card.

DisplayPort[™] to VGA, DisplayPort[™] to DVI (single-link and dual-link), and DisplayPort[™] to HDMI adapters available as accessories.

Maximum Resolution 5K support @ 60Hz

1x single-cable 5K monitor, or 2x dual-cable 5K monitors

Technical Specifications - Graphics

Image Quality Features HDR support over DisplayPort™ 1.4 (SMPTE 2084/2086,

BT. 2020) (4K @ 60 Hz 10b/12b HEVC Decode, 4K @ 60

Hz 10b HEVC Encode)

HDCP 2.2 support over DisplayPort™ and HDMI

connectors

NVIDIA 3D Vision™ technology

NVIDIA Mosaic and nView Desktop Management

Display Outputs 4x DP1.4 HDR2 outputs (up to 5120 x 2880 @ 60Hz)

GPU Architecture NVIDIA® Volta™

Supported Graphics

APIs

DirectX®12, OpenGL® 4.5

Developer API support includes: CUDA C, CUDA C++, DirectCompute

5.0, OpenCL™, Java, Python, and Fortran

Available Graphics

Drivers

Windows 11 Windows 10

Windows 7 (via nvidia.com)

Linux® 64-bit

HP qualified drivers may be preloaded or available from the HP

support Web site:

http://welcome.hp.com/country/us/en/support.html

Factory Configured (Z4/Z8 G4 Workstation): No adapters included

After market option kit: No adapters included

AMD Radeon™ Pro W5700 Form Factor

8GB Graphics

Dual Slot (4.4" Height x 10.5" Length)

Graphics Controller Radeon™ Pro W5700 graphics

GPU: 2304 Stream Processors

Power: 205 Watts Cooling: Active

Memory 8GB GDDR6 memory

Memory Bandwidth: Up to 448 GB/s

Memory Width: 256 bit

Connectors 5x MiniDisplayPort 1.4 + USB-C – HDR ready and MST support

Factory Configured: No video cable adapter included After market option kit: 2x mDP-to-DP adapters included

Additional DisplayPort-to-VGA or DisplayPort-to-DVI adapters are

available as Factory Configuration or Option Kit accessories.

Technical Specifications - Graphics

Maximum Resolution 8K support @ 60Hz

Single monitor, single or dual-cable

Image Quality Features Advanced support for 8-bit, 10-bit, and 16-bit per RGB color component.

High bandwidth scaler for high quality up and downscaling

Display Output 5 full physical mDP 1.4 + USB-c with DP signaling

FreeSync support

GPU Architecture RDNA™

Supported Graphics APIs DirectX° 12.1

OpenGL[®] 4.6 OpenCL™ 2.0 Vulkan™ 1.1

Available Graphics Drivers Windows 11

Windows 10

Linux® 64-bit

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

Notes

AMD Radeon™ Pro W5500 Form Factor

8GB Graphics

Single Slot (4.4" Height x 9.5" Length)

Graphics Controller Radeon™ Pro W5500 graphics

GPU: 1408 Stream Processors

Power: 125 Watts Cooling: Active

Memory 8GB GDDR6 memory

Memory Bandwidth: Up to 224 GB/s

Memory Width: 128 bit

Connectors 4x DisplayPort 1.4 – HDR ready and MST support

Factory Configured: No video cable adapter included After market option kit: No video cable adapter included

Additional DisplayPort-to-VGA or DisplayPort-to-DVI adapters are

available as Factory Configuration or Option Kit accessories.

Maximum Resolution 8K support @ 60Hz



Technical Specifications - Graphics

Single monitor, single or dual-cable

Image Quality Features Advanced support for 8-bit, 10-bit, and 16-bit per RGB color component.

High bandwidth scaler for high quality up and downscaling

Display Output 4 full physical DP 1.4

FreeSync support

GPU Architecture RDNA™

Supported Graphics APIs DirectX° 12.1

OpenGL[®] 4.6 OpenCL™ 2.0 Vulkan™ 1.1

Available Graphics Drivers Windows 11

Windows 10

Linux® 64-bit

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

Notes

AMD Radeon™ Pro W6800 32GB Form Factor Full-Height Double Slot

Graphics Controller Architecture: RDNA 2

GPU Cores: 3840 Power: 261W

Cooling: Active fan heatsink

Memory 32GB GDDR6 memory

ECC Capable: Yes

Memory Bandwidth: up to 512 GB/s

Memory Interface: 256-bit

Display Output Max Displays: 6

Video Output: 6x Mini-DisplayPort™ 1.4 with DSC

Display Configurations:

5K Resolution: 6x @ 5120 x 2880 resolution @ 60Hz 8K Resolution: 2x @ 7680 x 4320 resolution @60Hz

HDR Support: Yes 8K Support: Yes

Notes: W6800 only has mini-DisplayPort™ (mDP) video ports

Technical Specifications - Graphics

- Configure-to-order must specify AV options to add any required mDP-to-DP Adapters
- Two mDP-to-DP Adapters are included in the RTX A2000 AMO kits
- If more mDP-to-DP Adapters are needed, Adapters can be ordered separately as AMO:
 - 2MY05AA HP Single miniDP-to-DP Adapter Cable
 - 2KW87A6 HP (Bulk 12) miniDP-to-DP Adapter Cables

Bus Type PCI Express x16 Gen4

Software API Support DirectX°: 12

OpenGL[®]: 4.6, OpenCL™: 2.1 Vulkan: 1.2

Available Graphics Drivers Windows 11

Windows 10

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

NVIDIA® Quadro® Sync II Part number 1WT20AA

Dimensions (HxD) 6.0 inches × 4.2 inches

Devices Supported NVIDIA® Quadro® P4000
NVIDIA® Quadro® P5000

NVIDIA® Quadro® P6000

Bus Type Requires one free mechanical PCIe bus slot. 6-pin PCI or SATA power

connector

PCI Form Factor Full Height, half length, single slot

Ports 2 RJ45 connectors for carrying frame lock signals over CAT5 cables.

BNC Connector for external house synchronization.

Internal Connectors 6 NVIDIA SLI® style edge fingers for connection to compatible GPUs

• Included with the board are 412-Inch Short Sync Cables to connect

to GPU's

Included with the board are 2 24-Inch Long Sync Cables to connect

to GPU's

System Requirements Requires one free mechanical PCIe bus slot. 6-pin PCI or SATA power

connector

Must be used with NVIDIA Quadro P4000, P5000 or P6000 graphics cards.

Requires Quadro driver version R375 or later.

Temperature - Operating 0° to 55° C **Temperature - Storage** -40° to 60° C **Relative Humidity -** 10% to 80%

Operating

Power Requirements Board power dissipation: <15W

Operating Systems Windows 11 Supported Windows 10 Windows 7

Technical Specifications - Graphics

Linux® 64-bit

Kit Contents

Contains:

- Quadro Sync II Card
- 4 x 12-Inch Short Sync Cables
- 2 x 24-Inch Long Sync Cables (Two)
- Quick Start Guide



Technical Specifications – Optical and Removable Storage

OPTICAL AND REMOVABLE STORAGE

HP 9.5mm Slim DVD Writer Description

Description 9.5mm height, tray-load **Mounting Orientation** Either horizontal or vertical

Interface Type SATA/ATAPI

Dimensions (WxHxD) 128 x 9.5 x 127mm

Supported Media Types DVD+R

DVD+RW DVD+R DL DVD-R DL DVD-R DVD-RW CD-R CD-RW

Disc Capacity DVD-ROM 8.5 GB DL or 4.7 GB standard

Full Stroke DVD < 200 ms (seek)
Full Stroke CD < 200 ms (seek)

Maximum Data Transfer

Rates

CD ROM Read CD-ROM, CD-R Up to 24X

CD-RW Up to 24X

DVD ROM Read DVD+RW Up to 8X

DVD-RW Up to 8X DVD+R DL Up to 8X DVD-R DL Up to 8X DVD-ROM Up to 8X DVD-ROM DL Up to 8X DVD+R Up to 8X DVD-R Up to 8X

Power Source SATA DC power receptacle

DC Power Requirements 5 VDC ± 5%-100 mV ripple p-p

DC Current 5 VDC -< 800 mA typical, <1600 mA

maximum

Operating Environmental (all conditions non-

condensing)

Supported

Operating Systems

Temperature

41° to 122° F (5° to 50° C)

Relative Humidity 10% to 80%

Maximum Wet Bulb Temperature 84° F (29° C)
Windows 11, Windows 10, Windows 7 Professional 64-bit,

Windows Vista Business 64*, Windows 2000.

Red Hat® Enterprise Linux® (RHEL) 6, 7 Desktop/Workstation

SUSE Linux® Enterprise Desktop 12

* No driver is required for this device. Native support is provided by the

operating system.

Kit Contents HP SATA DVD Writer drive, installation guide.

HP 9.5mm Slim DVD-ROM Drive

Mounting Orientation

Description

9.5mm height, tray-load
Either horizontal or vertical



Technical Specifications — Optical and Removable Storage

Interface Type SATA / ATAPI Dimensions (WxHxD) 128 x 9.5 x 127mm

Disc Capacity DVD-ROM Single layer: Up to 4.7 GB

Double layer: Up to 8.5 GB

Access Times **DVD-ROM Single Layer** < 110 ms (typical)

> CD-ROM Mode 1 < 110 ms (typical) Full Stroke DVD < 230 ms (typical) Full Stroke CD < 220 ms (typical)

Power SATA DC power receptacle Source

> **DC Power Requirements** 5 VDC ± 5%-100 mV ripple p-p

DC Current 5 VDC - <800mA typical, < 1600 mA

maximum

Operating Environmental Temperature

(all conditions noncondensing)

41° to 122° F (5° to 50° C)

Relative Humidity 10% to 80% Maximum Wet Bulb Temperature 84° F (29° C)

Operating Systems

Supported

Windows 11, Windows 10, Windows 8.1, Windows 7 Professional 64-bit

Red Hat® Enterprise Linux® (RHEL) 6, 7 Desktop/Workstation

SUSE Linux® Enterprise Desktop 12

No driver is required for this device. Native support is provided by the

operating system.

Kit Contents 9.5mm Slim DVD-ROM Drive, 5.25" ODD Bay adapter/carrier, slim SATA

data/power cable, installation guide

HP HH DVD Writer (16X RW Description

DVD-R)

Mounting Orientation

HP Half Height DVD Writer Either Horizontal or vertical

Interface Type SATA

Dimensions (WxHxD) 146x42x165mm

Supported Media Types DVD+R

> DVD+RW DVD+R DL DVD-R DL DVD-R **DVD-RW** CD-R CD-RW

Disc Capacity DVD-ROM 8.5 GB DL or 4.7 GB standard

> Full Stroke DVD 145ms (seek) Full Stroke CD 120ms (seek)

Maximum Data Transfer

Rates

CD ROM Read

CD-ROM, CD-R Up to 24X

CD-RW Up to 24X

DVD ROM Read DVD+RW Up to 13X

> DVD-RW Up to 13X DVD+R DL Up to 12X DVD-R DL Up to 12X DVD-ROM Up to 12X



Technical Specifications – Optical and Removable Storage

DVD-ROM DL Up to 12X DVD+R Up to 16X

DVD-R Up to 16X

Power Source SATA DC power receptacle

> **DC Power Requirements** 5 VDC ± 5% -100 mV ripple p-p

12 VDC ± 10% -200 mV ripple p-p

DC Current 5 VDC -<1500mA typical, <2000 mA

maximum.

Operating Environmental

(all conditions non-

condensing)

Relative Humidity

Temperature

41° to 122° F (5° to 50° C) 10% to 90% (Non-Condensing)

Operating Systems Supported

Windows 11, Windows 10, Windows 7 Professional 64-bit. Red Hat

Enterprise Linux WS4**,5,6 Desktop/Workstation.

No driver is required for this device, Native support is provided by

operating system.

HP SATA DVD Writer drive, Installation guide. Kit Contents

HP 9.5mm Slim BDXL Blu- Description **Ray Writer**

9.5mm height, tray-load

Mounting Orientation Either horizontal or vertical

Interface Type SATA/ATAPI Dimensions (WxHxD) 128 x 9.5 x 127mm

Supported Media Types

BD-ROM

BD-R **BD-RE** DVD+R DVD+RW DVD+R DL DVD-R DL DVD-R

DVD-RW CD-R CD-RW

Disc Capacity

DVD-ROM Blu-ray

8.5 GB DL or 4.7 GB standard

25 GB (single-layer)

50 GB (dual-laver) 100/128 GB (BDXL)

Full Stroke DVD < 230 ms (seek) Full Stroke CD < 220 ms (seek)

Blu-ray < 230 ms (seek) (Full Stroke Blu-ray)

Startup Time (Time to drive ready from tray

loading)

BD-ROM (SL/DL) 255 / 285 BD-R (SL/DL) 255 / 285 BD-RE (SL/DL) 255 / 285 DVD-ROM (SL/DL) 185 / 185 DVD-R (SL/DL) **25S / 25S**

DVD-RW **25S**

DVD+R (SL/DL) 25S / 25S



Technical Specifications – Optical and Removable Storage

DVD+RW 25S CD-ROM 15S

Maximum Data Transfer

Rates

CD ROM Read

CD-ROM, CD-R Up to 24X

CD-RW Up to 24X

DVD ROM Read DVD+RW Up to 8X

DVD-RW Up to 8X
DVD+R DL Up to 8X
DVD-R DL Up to 8X
DVD-ROM Up to 8X
DVD-ROM DL Up to 8X
DVD-R Up to 8X
DVD-R Up to 8X
DVD-R Up to 8X

Blu-ray BD-ROM Up to 6X

BD-ROM DL Up to 6X BD-R Up to 6X BD-R DL Up to 6X BD-R Up to 6X BD-RE SL/DL Up to 6X

Power Source SATA DC power receptacle

DC Power Requirements 5 VDC ± 5%-100 mV ripple p-p

DC Current 5 VDC -900 mA typical, 2000mA

maximum

Operating Environmental

(all conditions noncondensing) Temperature

41° to 122° F (5° to 50° C)

Relative Humidity 10% to 80% Maximum Wet Bulb Temperature 84° F (29° C)

Operating Systems

Supported

Windows 11, Windows 10, Windows 7 Professional 64-bit, Red Hat® Enterprise Linux® (RHEL) 6, 7 Desktop/Workstation

SUSE Linux® Enterprise Desktop 12

No driver is required for this device. Native support is provided by the

operating system.

Kit Contents 9.5mm Slim BDXL Blu-Ray Writer, 5.25" ODD Bay adapter/carrier, slim

SATA data/power cable, installation guide

As Blu-ray is a new format containing new technologies, certain disc, digital connection, compatibility and/or performance issues may arise, and do not constitute defects in the product. Flawless playback on all systems is not guaranteed. In order for some Blu-ray titles to play, they may require a DVI or HDMI digital connection and your display may require HDCP support. HD-DVD movies cannot be played on this workstation.

HP SD Card Reader

Description Supports hardware ECC (Error Correction Code) function

Supports hardware CRC (Cyclic Redundancy Check) function

Supports SD 4-bit parallel transfer mode

Interface Type USB 3.1 Gen 1 High-speed interface

Dimensions (WxHxD) 1.15 x .9 x .15 in (29.00 x 23.6 x 3.15 mm) Fits conveniently in the Front IO

Bay

Supported Media Types Secure Digital Card (SD)

Secure Digital High Capacity (SDHC)



Technical Specifications – Optical and Removable Storage

SD Extended Capacity Memory Card (SDXC)

SD Ultra High Speed II(SD UHSII)

These additional media types are supported with a card adapter.

Memory Stick Micro (M2)

miniSD

miniSD High Capacity

Micro SD Memory Card (MicroSD)

Micro SD High Capacity Memory Card (MicroSDHC)

Test Parameters/Conditions - Power applied, unit operating on system

±5%

Operating Systems
Supported

Windows 11, Windows 10

No driver is required for this device. Native support is provided by the

operating system.

Kit Contents Media card reader

Approvals USB-IF, WHQL, Compliant with USB Mass Storage Class Bulk only Transport

Specification Rev. 1.0,

Compliant Intel Front Panel I/O Connectivity Design Guide V. 1.3, FCC, CE,

BSMI, C-Tick, VCCI, MIC, cUL, TUVT

Weight 0.35 lbs. (0.16 kg)



Technical Specifications - Controller Cards

CONTROLLER CARDS

HP Thunderbolt-3 Dual Data Transfer Rate Port2 PCIe 1-port I/O Card Devices Supported

Data Transfer Rate Supports up to 40 Gb/s (40,000 Mb/s)

Devices Supported Thunderbolt™, Thunderbolt™ 2 and Thunderbolt™ 3 certified for Windows

devices

Bus Type PCIe card, full height PCIe slots

Ports Two Thunderbolt™ 3 external USB type-C output connectors (Rear)

Two full size DisplayPort input connectors (Rear)

Internal Connectors One 2x5-Pin header connector

System Requirements Windows 11, Windows 10 Professional, available dedicated PCH PCIe slot.

Temperature - Operating 50° to 131° F (10° to 55° C) **Temperature - Storage** -22° to 140° F (-30° to 60° C)

Relative Humidity -

Operating

20% to 80%

Compliances FCC Part 15B, cULus 60950, CE Mark EN55022B(1995)/EN55024-1998 STD,

Taiwan BSMI CNS13438, Korea MIC

Operating Systems

Supported

Windows 11, Windows 10 Professional.

Kit Contents HP Thunderbolt™ 3 Dual Port PCIe I/O Card, 2- DisplayPort cables, GPIO

(General-Purpose Input/Output) cables, Installation documentation and

warranty card.

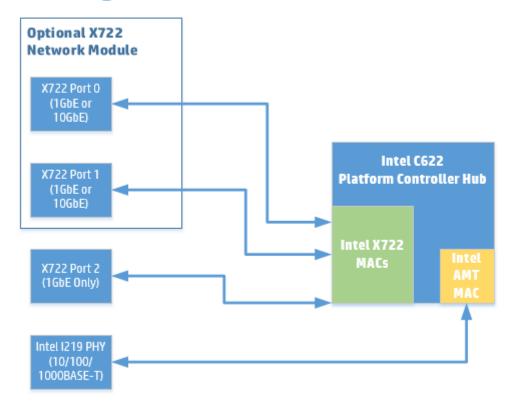


^{*}Maximum speed requires DisplayPort™ and PCIe aggregation.

Technical Specifications - Networking and Communications

NETWORKING AND COMMUNICATIONS

HP Z6 Gen4 and HP Z8 Gen 4 Integrated Network Architecture



Note: When an optional X722 network module is not installed in the system, a "dummy" port is enumerated as Function 0 of the Intel X722 MACs, which allows for the X722 Port 2 on the Motherboard to enumerate.

Integrated Intel I219LM

Connector RJ-45
Controller Intel I219LM
Data Rates Supported 10/100/1000 Mbps
Boot ROM Support PXE, UEFI

Indicators

Connect Speed LED Link/Activity LED

• Off = No link

Blinking = Activity

Speed LED

Off = 10Mbps

Amber = 100Mbps

Green = 1000Mbps

Management Capabilities Intel® Active Management Technology™ 11



Technical Specifications - Networking and Communications

Integrated Intel X722 for 1GbE

Connector

1 RJ-45

Controller

Intel X722 for 1GbE

Data Rates Supported Boot ROM Support

1000 Mbps PXE, UEFI

Connect Speed LED

Indicators

Link/Activity LED Off = No link

Blinking = Activity

Speed LED

Off = No Link

Green = 1000Mbps

Management Capabilities Wake-On-LAN

HP Z Dual 10GbE Network Networking Interface Module

2 RJ-45

System Interface

Cabled from Dedicated Rear I/O Slot

Networking Speeds

Supported

1Gbps, 10Gbps

Cabling (up to 100m)

Cat5e (or higher) for 1Gbps

Cat6a (or higher) for 10Gbps

Power Consumption

(active-typical)

5.5W at 1Gbps 11.2W at 10Gbps

Physical Dimensions

0.875 in x 3 in x 2.75 in

Connect Speed LED

Link/Activity LED Off = No link

Indicators

Blinking = Activity

Speed LED

Amber = 1Gbps

Green = 10Gbps

Operating Temperature

0 °C to 55 °C (32 °F to 131 °F)

Intel® I210-T1

Networking Interface

1 RJ-45

System Interface

PCI Express 2.1 x1

Networking Speeds

10Mbps, 100Mbps, 1Gbps

Supported

Cabling (up to 100m)

Cat3 (or higher) for 10Mbps Cat5 (or higher) for 100Mbps

Cat5e (or higher) for 1Gbps

Power Consumption

0.81W

(active-typical)

Length: 6.7cm (2.64 inches)

Physical Dimensions (Bracket) Width: 1.8cm (0.709 inches)

> Full-height end bracket: 12.07cm (4.755 inches) Low-profile end bracket: 8cm (3.15 inches)

Technical Specifications - Networking and Communications

Connect Speed LED Indicators

Link/Activity LED

Off = No link

• Blinking = Activity

Speed LED

Off = 10Mbps

Green = 100Mbps

Amber = 1Gbps

Operating Temperature

0 °C to 55 °C (32 °F to 131 °F)

Hardware Certifications

USA: FCC B, EU: UL CE, Japan: VCCI, Taiwan: BSMI,

Australia/New Zealand: CTICK,

Korea: KCC,

Canada: ICES-003/NMB-003

Intel® 1350-T2

Networking Interface

2 RJ-45

System Interface

PCI Express 2.1 x4

Networking Speeds

Supported

10Mbps, 100Mbps, 1Gbps

Cabling (up to 100m)

Cat3 (or higher) for 10Mbps Cat5 (or higher) for 100Mbps Cat5e (or higher) for 1Gbps

Power Consumption (active-typical)

4.4W

Physical Dimensions

Length: 13.54cm (5.33 inches) Width: 6.89 (2.71 inches)

Full-height end bracket: 12.0cm (4.725 inches) Low-profile end bracket: 7.92cm (3.117 inches)

Connect Speed LED Indicators

Link/Activity LED

• Off = No link

• Blinking = Activity

Speed LED

• Off = 10Mbps

Green = 100Mbps

Amber = 1Gbps

Operating Temperature Hardware Certifications 0 °C to 55 °C (32 °F to 131 °F)

USA: FCC B, EU: UL CE, Japan: VCCI,

Japan: vcci, Taiwan: BSMI,

Australia/New Zealand: CTICK,

Korea: KCC,

Canada: ICES-003/NMB-003

Intel® 1350-T4

Networking Interface

4 RJ-45

System Interface

PCI Express 2.1 x4

Networking Speeds Supported 10Mbps, 100Mbps, 1Gbps



Technical Specifications - Networking and Communications

Cabling (up to 100m) Cat3 (or higher) for 10Mbps

> Cat5 (or higher) for 100Mbps Cat5e (or higher) for 1Gbps

Power Consumption (active-typical)

5W

Physical Dimensions

Length: 13.54cm (5.33 inches) Width: 6.89 (2.71 inches)

Full-height end bracket: 12.0cm (4.725 inches) Low-profile end bracket: 7.92cm (3.117 inches)

Connect Speed LED Indicators

Link/Activity LED Off = No link

Blinking = Activity

Speed LED

Off = 10Mbps Green = 100Mbps Amber = 1Gbps

Operating Temperature Hardware Certifications

0 °C to 55 °C (32 °F to 131 °F)

USA: FCC B. EU: UL CE, Japan: VCCI. Taiwan: BSMI,

Australia/New Zealand: CTICK,

Korea: KCC.

RJ-45

Canada: ICES-003/NMB-003

Aquantia® AQN-108

Networking Interface

System Interface PCI Express 3 x1

Networking Speeds

Supported

Cabling (up to 100m) **Power Consumption**

(active-typical)

Physical Dimensions Connect Speed LED

Indicators

100Mbps, 1Gbps, 2.5Gbps, 5Gbps

Cat5e (or higher) for all speeds

3.5W at 5Gbps, 3.0W at 2.5Gbps

3.72 in x 3.18 in (without bracket)

Link/Activity LED

Off = No link

Blinking = Activity

Speed LED

Off = No link

Amber = <5Gbps

Green = 5Gbps

Operating Temperature Hardware Certifications

0 °C to 55 °C (32 °F to 131 °F)

USA: FCC B, EU: UL CE, Japan: VCCI, Taiwan: BSMI,

Australia/New Zealand: CTICK,

Korea: KCC.

Canada: ICES-003/NMB-003

Technical Specifications - Networking and Communications

Intel® X550-T2 **Networking Interface** 2 x RJ-45

> **System Interface** PCI Express 3 x4

Networking Speeds

Supported

100Mbps, 1Gbps, 2.5Gbps, 5Gbps, 10Gbps

Cabling (up to 100m) Cat5 (or higher) for 100Mbps

Cat5e (or higher) for 1Gbps, 2.5Gbps, or 5Gbps

Cat6a (or higher) for 10Gbps

Power Consumption (active-typical)

3.9W at 100Mbps 5.5W at 1Gbps 11.2W at 10Gbps

Physical Dimensions Connect Speed LED

Indicators

5.2 in x 2.7 in (without bracket)

Link/Activity LED Off = No link

Blinking = Activity

Speed LED

Off = No link

Amber = <10Gbps

Green = 10Gbps

Operating Temperature

0 °C to 55 °C (32 °F to 131 °F)

Hardware Certifications

USA: FCC B. EU: UL CE, Japan: VCCI. Taiwan: BSMI,

Australia/New Zealand: CTICK.

Korea: KCC.

Canada: ICES-003/NMB-003

Allied Telesis AT-2914SX/LC-901 1GB LC Fiber NIC

Network Interface System Interface Networking Speeds Supported

1Gb LC Fiber 850 nm

PCIeG2 x1, Half Height, Half Length

1000Base-X (1Gbps)

Cabling 50/125 µm (core/cladding) multimode fiber optic cable up to 500m 62.5/125 µm (core/cladding) multimode fiber optic cable up to 220m

Power Consumption (active-typical) **Physical Dimensions Connect Speed LED**

1.5 Watts

8.8 cm x 6.9 cm (3.5 in x 2.7 in) ON: 1Gbps Link OFF: Link down

Indicators

Operating Temperature Hardware Certifications

-25°C to 70°C (-13°F to 158°F)

IEEE 802.1p (Quality of Service), IEEE 802.1Q (VLANs), IEEE 802.2 (LLC), IEEE 802.3ac (MAC), IEEE 802.3x (Flow control auto-negotiation), IEEE

802.3z (1000 Base-X), IEEE 802.3ad (Link aggregation)

RoHS, UL, FCC/EN55022 Class A, TUV, EN55024, CE, C-TICK, VCCI

Intel® X710-DA2 10GBASE-SR Converged **Network Adapter**

Networking Interface System Interface

2 SFP+ Ports for LC SFP+ Transceivers

PCI Express 3.0 x8



Technical Specifications - Networking and Communications

Networking Speeds

Supported

1Gbps, 10Gbps

Cabling

LC fiber optic cabling with LC SFP+ Transceivers

Power Consumption

(active-typical)

4.3W

Physical Dimensions Connect Speed LED

Indicators

Link/Activity LED Off = No link

6.578 in x 2.703 in

Blinking = Activity

Speed LED

Off = 10Mbps

Green = 100Mbps

Amber = 1Gbps

Operating Temperature

0 °C to 55 °C (32 °F to 131 °F)

Hardware Certifications

USA: FCC B, EU: UL CE, Japan: VCCI,

Taiwan: BSMI.

Australia/New Zealand: CTICK,

Korea: KCC,

Canada: ICES-003/NMB-003

Note: Windows 7 is NOT supported

10GbE SFP+ SR **Transceiver**

Connector Type

LC

Cable Type

62.5/125um or 50/125um (core/cladding), graded-index, low metal

content, multimode fiber optic, complying with ITU-T G.651 and ISO/IEC

793-2 Type A1b or A1a, respectively.

Cable Length 2-300m Wavelength 850nm Form Factor SFP+

Physical Dimensions

0.47(h) x 0.54(w) x 2.19(d) inches

(1.19 x 1.38 x 5.57 cm)

Operating Temperature

OC to 45C (32F to 113F)

Operating Humidity

0% to 85%, noncondensing

Intel® 8265 WLAN

Networking Speeds

802.11ac MU-MIMO (up to 867 Mbps)

Bluetooth 4.2

IEEE WLAN Standard

IEEE 802.11a/b/g/n/ac, 802.11d, 802.11e, 802.11h, 802.11i, 802.11w;

802.11r, 802.11k, 802.11v pending

Bluetooth 4.2

System Interface PCI Express 2.1 x1

Antenna 2x2

Intel® 9260 WLAN

Networking Speeds

802.11ac MU-MIMO (up to 1.73Gbps using 160MHz channels)



Technical Specifications - Networking and Communications

IEEE WLAN Standards IEEE 802.11a/b/g/n/ac

Bluetooth 5.0

System Interface PCI Express 2.1 x1

Antenna 2x2



Summary of Changes

SUMMARY OF CHANGES

Date of change:	Version History:		Description of change:
	From v1 to v2	Added	Specs for the Power Supply section
		Changed	The System Configurations section and changed notes for the NVIDIA
			Quadro P4000, P5000 & P6000 Graphics
November 1, 2017	From v2 to v3	Added	HP DisplayPort to HDMI Adapter, NVIDIA SLI 2-slot Graphics Connector and
			NVIDIA Quadro Sync II to Graphics section
		Changed	Graphics, Storage / Hard Drives, Networking and Communications, Other
			Hardware and Memory sections, changed Front view info on the Overview
			section, changed Operating Systems section, changed Processors section,
			changed System Board section, Physical Security and Serviceability section
	From v3 to v4	Added	Windows 10 to the supporting systems by the 9.5mm Slim DVD-ROM drive
		Removed	Microsemi 3152-8i SAS ROC RAID Controller from SAS controller on the
			Hard Drive Controllers section.
November 29, 2017	From v4 to v5	Added	Processors, hard drives and graphics to offerings, added Declared Noise
			Emissions information
		Changed	Wattage links on power supply section updated and Voltage links on
			efficientcy section updated
January 30, 2018	From v5 to v6	Changed	Factory configured option to yes on Networking and communications for :
			Intel® 8265 802.11 a/b/g/n/ac&BT PCIe
		Removed	NVIDIA SLI Graphics Connector from Graphics Cable Adapters section
February 14, 2018	From v6 to v7	Removed	RAID 5 and 10 references from "Factory integrated" in interfaces supported
			section
March 27, 2018	From v7 to v8	Added	NVIDIA Quadro GP100 16GB Graphics, NVIDIA Quadro GV100 32GB Graphics
			and AMD Radeon Pro WX 9100 16GB Graphics as High End 3D in Graphics
			section
		Added	Intel Xeon processors added
August 13, 2018	From v8 to v9	Added	Footnote to Networking and Communications section
		Changed	Operating Systems section
September 6, 2018	From v9 to v10	Added	Integrated Network Architecture Diagram on The Networking and
			Communications section
September 6, 2018	From v10 to v11	Changed	Power Supply section
September 21, 2018	From v12 to v13	Added	Intel Optane SSD 905p AiC 280GB & 480GB
November 19, 2018		Added	Intel Xeon Gold 6128 processor
		Changed	NVIDIA Quadro P6000 Graphics specs
January 2, 2019	From v13 to v14	Added	NVIDIA Quadro P620 2GB Graphics
January 8, 2019	From v14 to v15	Added	HP DX175 Removable HDD Carrier into the HDD Frame/Carriers section
		Changed	Intel Xeon Gold 6126 processor specs
January 9, 2019	From v15 to v16	Added	Intel Xeon Gold 6126 processor footnote
January 23, 2019	From v16 to v17	Added	Intel 9260 802.11 a/b/g/n/ac&BT PCIe to Networking section and added HP
			Z Turbo Drive Dual Pro series to Storage section
April 8, 2019	From v17 to v18	Added	New Intel Xeon Processors and graphics
		Changed	Storage / Hard Drives, Memory sections and format changes
May 15, 2019	From v18 to v19	Added	NVIDIA Quadro RTX 8000 48GB Graphics
		Changed	Networking and Communications section and changed External BIOS
			simulator link on Physical Security and Serviceability section
June 12, 2019	From v19 to v20	Changed	Storage section Storage Section Storage Section Storage Section Sectio
July 15, 2019	From v20 to v21	Changed	Corrected Intel 905p Series AIC 480GB PCIe SSD
August 1, 2019	From v21 to v22	Changed	Processors Matrix
August 6, 2019	From v22 to v23	Changed	Graphics section
September 1, 2019	From v23 to v24	Added	Footnote to Memory section, Added Optane 905P 380GB M.2 SSD Module,
			HP Z Turbo Drive 1TB SED TLC Z8 G4 SSD Kit & module to Storage section,
			Added Intel® Wi-Fi 6 AX200 & BT PCIe to Networking section



Summary of Changes

October 26, 2019	From v24 to v25	Changed	Graphics section
November 2, 2019	From v25 to v26	Added	NVDIMM Memory sections, Added HP QX310 Removable NVMe
110101111111111111111111111111111111111	110111 125 10 120	ridaca	Frame/Carrier w/PCIe card to Optical and Removable Storage section
January 15, 2020	From v26 to v27	Changed	Storage section
February 26, 2020	From v27 to v28	Added	New Intel Xeon Processors
20, 44, 7	110111127 (0120	Changed	Overview, PCIe Solid State Drives sections
April 2, 2020	From v28 to v29	Changed	Processors and NVDIMM Memory sections
July 18, 2020	From v29 to v30	Changed	Processors, Graphics section
January 5, 2021	From v30 to v31	Changed	Processors, Memory, Graphics, Racking and Physical Security, Operating
, ,			Systems and Hard Drives sections
January 7, 2021	From v31 to v32	Changed	Format
February 1, 2021	From v32 to v33	Added	NVIDIA® RTX A6000 48GB to Graphics section
		Changed	NETWORKING AND COMMUNICATIONS section
March 1, 2021	From v33 to v34	Changed	Overview, Graphics and System Board sections
April 13, 2021	From v34 to v35	Changed	Graphics and Social and Environmental Responsibility sections
May 1, 2021	From v35 to v36	Changed	Graphics section
May 20, 2021	From v36 to v37	Changed	Graphics section
June 1, 2021	From v37 to v38	Changed	Memory and Graphics sections
July 1, 2021	From v38 to v39	Changed	Graphics section
July 15, 2021	From v39 to v40	Changed	PCIe Solid State Drives section
July 16, 2021	From v40 to v41	Changed	PCIe Solid State Drives section
August 1, 2021	From v41 to v42	Changed	Graphics section
October 1, 2021	From v42 to v43	Changed	Input Devices, Graphics and System Board sections
November 1, 2021	From v43 to v44	Changed	Processors and Graphics sections
December 1, 2021	From v44 to v45	Changed	Operating Systems, Graphics, Networking and Communications and Input
			Devices sections
December 15, 2021	From v45 to v46	Changed	OPERATING SYSTEM and Social and Environmental Responsibility sections
January 1, 2022	From v46 to v47	Changed	Graphics, OPERATING SYSTEM and Application Software sections
February 1, 2022	From v47 to v48	Added	Intel® Xeon® Gold 6234 to Processors section
		Changed	Input Devices section
March 1, 2022	From v48 to v49	Changed	Graphics, Social and Environmental Responsibility sections



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